

RX Family

Flash Module Using Firmware Integration Technology

Introduction

This application note describes a flash module which uses Firmware Integration Technology (FIT)*1. This module has been developed to allow users of supported devices to easily integrate reprogramming of internal flash memory into their applications using self-programming*2.

This application note focuses on using this module and integrating it with your application program.

- ^{*1} This module is different from the "Simple Flash API for RX (R01AN0544)".
- ^{*2} Self-programming is a method of reprogramming flash memory using user applications.

Target Devices

- RX110 Group
- RX111 Group
- RX113 Group
- RX130 Group
- RX13T Group
- RX140 Group
- RX230, RX231 Groups
- RX23E-A Group
- RX23T Group
- RX23W Group
- RX24T GroupRX24U Group
- RX64M Group
- RX65N, RX651 Groups
- RX66N Group
- RX66T Group
- RX671 Group
- RX71M Group
- RX72M Group
- RX72N Group
- RX72T Group

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

Target Compilers

- Renesas Electronics C/C++ Compiler Package for RX Family
- GCC for Renesas RX
- IAR C/C++ Compiler for Renesas RX

For details of the confirmed operation contents of each compiler, refer to "5.1 Confirmed Operation Environment".

Related Documents

- Firmware Integration Technology User's Manual (R01AN1833)
- Board Support Package Firmware Integration Technology Module (R01AN1685)



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1. Overview

1.1 Flash Module Overview

This module was designed so that the flash memory (code flash memory and data flash memory) embedded in the MCU can be reprogrammed.

An API function used to reprogram flash memory is provided with this module.

1.1.1 Flash Types Overview

Flash memory is categorized by the features supported by MCU. Table 1.1 summarizes the categories relevant to this module.

Table 1.1 Supported MCU Groups by Flash Type

Flash Type	Supported MCU Groups
1	RX110 ^{*1} , RX111, RX113, RX130, RX13T, RX140
	RX230, RX231, RX23E-A, RX23T ^{*1} , RX23W, RX24T, RX24U
3	RX64M, RX66T, RX71M, RX72T
4	RX651*2, RX65N*2, RX66N, RX671, RX72M, RX72N

^{*1} No data flash memory.

^{*2} No data flash memory in products 1 Mbyte or less of code flash memory.

1.1.2 Supported Features

Table 1.2 describes the flash types that are required for the features supported by this module.

Table 1.2 Supported Features by Flash Type

Functionality	Overview	Flash Type			
		1	3	4	
Program	Programs the specified region.	~	•	~	
Erase	Erases the specified region.	•	~	V	
Blank check	Checks that a specified region is not programmed.	*1	*1	*1	
Access window	Sets only specified regions as reprogrammable so as to protect other regions.	*2	_	*2	
Startup program protection	Swaps the region containing the startup program after a reset to protect the startup region.	*3	_	<i>'</i>	
Lockbit	Enables/disables a specified region as reprogrammable to protect the specified regions.	_	✓ *4	_	
ROM cache	Enables/disables the code flash memory cache.	*5	*6	V	
Disable cache	Sets regions for which cache is disabled.	_	*6	✓ *7	
Dual bank	Swaps the startup bank.	_	_	V	
Flash sequencer reset	Resets the flash sequencer.	~	~	~	
Flash sequencer usage frequency notification	Provides notification of the frequency used by the flash sequencer.	_	~	~	

^{*1} Only Flash Type 1 supports blank checks on code flash memory.



^{*2} Access window can only be used on code flash memory.

^{*3} Only supported on products with at least 32 Kbytes of code flash memory.

^{*4} Lockbit can only be used on code flash memory.

^{*5} Supported by RX24T and RX24U only.

^{*6} Supported by RX66T and RX72T only.

^{*7} Supported by RX66N, RX671, RX72M, and RX72N only.

1.2 API Overview

Table 1.3 describes information on the API information embedded in this module.

Table 1.3 API Functions

Function	Description of Function
R_FLASH_Open()	Initializes this module.
R_FLASH_Close()	Closes this module.
R_FLASH_Erase()	Erases specified blocks in data flash memory or code flash memory.
R_FLASH_BlankCheck()	Checks that specified regions in data flash memory or code flash memory have
	not been programmed.
R_FLASH_Write()	Programs specific data into specified regions in data flash memory or code flash
	memory.
R_FLASH_Control()	Performs functionality other than programming, erasing, and blank check.
R_FLASH_GetVersion()	Returns the current version of this module.

1.3 Limitations

1.3.1 Flash Memory Access Restrictions

The flash sequencer has a read mode for reading the flash memory and a P/E mode for reprogramming the flash memory.

Table 1.4 describes the regions that can and cannot be read during P/E mode.

Table 1.4 Regions With/Without Read Access During P/E Mode

Region Accessed During P/E Mode	Regions Without Read Access	Regions With Read Access*1
Code flash memory	Code flash memory	Data flash memory
		RAM
		External memory
		Other code flash memory*2
Data flash memory	Data flash memory	Code flash memory
		RAM
		External memory

^{*1} Excluding data flash memory, reprogramming code and interrupt vector tables should be allocated in regions with read access.

Refer to section 2.16.1 for more information on running reprogramming code from RAM.

Refer to section 2.16.2 for more information on reprogramming code flash memory with data in other code flash memory.

Refer to Example 1 in section 3.6 for more information on reallocating interrupt vector tables and interrupt processing.

1.3.2 RAM Allocation Restrictions

With FIT, configuring pointer arguments of API functions with values equivalent to NULL values results in parameter checks sometimes producing return errors. As such, do not set values of pointer arguments passed to API functions to values equivalent to NULL values.

The NULL value is defined in standard library specifications as zero (0). As such, the issue above will occur if variables and functions passed to API function pointer arguments are stored in starting addresses (0x0 addresses) in RAM. In this case, change the configuration of sections or create dummy variables to be stored at the beginning of RAM to prevent variables and functions passed to API function pointer arguments from being stored at 0x0 addresses.

CCRX projects (e² studio V7.5.0) are configured so that 0x4 is the starting RAM address to prevent variables from being stored at the 0x0 address. This issue must be prevented in case of GCC projects (e² studio V7.5.0) and IAR projects (EWRX V4.12.1) because the starting RAM address is set to 0x0.

Default section settings may need to be changed whenever the IDE is upgraded. Make sure to always check section settings before using the latest version of your IDE.

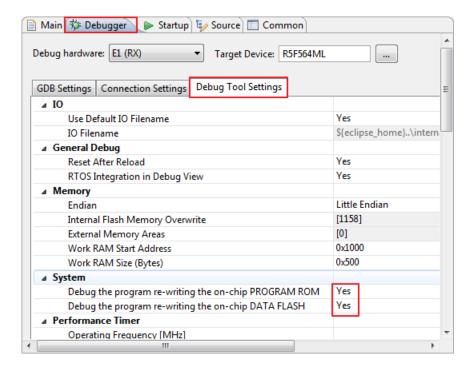


^{*2} Products with multiple regions of code flash memory.

1.3.3 Emulator Debug Configuration Restrictions

To confirm the data written to code flash memory and data flash memory during debug, change the Debug Tool Settings of the debug configuration as follows.

- 1. In Project Explorer, click the project you want to debug.
- 2. Click Execute -> Debug Configuration to open the Debug Configuration window.
- 3. On the Debug Configuration window, expand the display of the "Renesas GDB Hardware Debugging" debug configuration and click the debug configuration you want to debug.
- 4. Switch to the "Debugger" tab, click the "Debug Tool Settings" in the "Debugger" tab and make the following settings.
 - System
 - Debug the program re-writing the on-chip PROGRAM ROM = "Yes"
 - Debug the program re-writing the on-chip DATA FLASH = "Yes"



2. API Information

This module has been confirmed to operate under the following conditions.

2.1 Hardware Requirements

This driver requires that your MCU supports the following peripheral(s):

• Flash memory (code flash memory and data flash memory)

2.2 Software Requirements

The driver is dependent on the following FIT module.

Board Support Package (r_bsp) v5.20 or later

2.3 Supported Toolchains

This module has been confirmed to work with the toolchain listed in 5.1 Confirmed Operation Environment.

2.4 Interrupt Vector

When the FLASH_CFG_DATA_FLASH_BGO or FLASH_CFG_CODE_FLASH_BGO configuration option (see section 2.7) is 1, the interrupts shown in Table 2.1 below are enabled.

Table 2.1 Interrupt Vectors Used in this Module

Flash Type	Interrupt Vector
1	FRDYI interrupt (vector no.: 23)
3, 4	FRDYI interrupt (vector no.: 23), FIFERR interrupt (vector no.: 21)

2.5 Header Files

All API calls and their supporting interface definitions are located in "r_flash_rx_if.h". This file should be included by all files which utilize the Flash Module.

The configuration options that can be set at build time are defined in the "r flash rx config.h" file.

2.6 Integer Types

This project uses ANSI C99 "Exact width integer types" in order to make the code clearer and more portable. These types are defined in stdint.h.



2.7 Configuration Overview

Configuring this module is done through the supplied r_flash_rx_config.h header file. Each configuration item is represented by a macro definition in this file. Each configurable item is detailed in the table below.

Table 2.2 Flash general configuration settings

Configuration of	options in r_flash_rx_config.h
FLASH_CFG_PARAM_CHECKING_ENABLE *Default value is "1".	Enables/disables the inclusion of parameter check processing into the code. A value of "0" omits parameter check processing from the code. A value of "1" includes parameter check processing in the code.
FLASH_CFG_CODE_FLASH_ENABLE *Default value is "0".	Enables/disables the inclusion of code used to program code flash memory regions. A value of "0" includes code used to program data flash memory regions only (no code flash memory regions). A value of "1" includes code used to program both code flash memory regions and data flash memory regions.
FLASH_CFG_DATA_FLASH_BGO *Default value is "0".	Specifies the processing method for data flash memory. A value of "0" processes data flash memory in blocking mode. A value of "1" processes data flash memory in non-blocking mode. When FLASH_CFG_CODE_FLASH_ENABLE is set to "1", make the same setting as FLASH_CFG_CODE_FLASH_BGO. Refer to 2.13 for details on blocking mode and non-blocking mode.
FLASH_CFG_CODE_FLASH_BGO *Default value is "0".	Specifies the processing method for code flash memory. A value of "0" processes code flash memory in blocking mode. A value of "1" processes code flash memory in non-blocking mode. When FLASH_CFG_CODE_FLASH_ENABLE is set to "1", make the same setting as FLASH_CFG_DATA_FLASH_BGO. Refer to 2.13 for details on blocking mode and non-blocking mode.
FLASH_CFG_CODE_FLASH_RUN_FROM_R OM*1 *Default value is "0".	Specifies the code location for running the program and erase features on flash memory. This option is enabled only when FLASH_CFG_CODE_FLASH_ENABLE is set to "1". If set to "0", the code for running the program and erase features on flash memory is stored and ran in RAM. Refer to section 2.16.1 for details. If set to "1", the code for running the program and erase features on flash memory is allocated and ran in code flash memory. Refer to section 2.16.2 for details.

^{*1} Supported only in products with multiple regions of code flash memory.



2.8 Code Size

The ROM size, RAM size, and the maximum stack size of this module are described in the following table. Separate examples are given for each type of product: Flash Type 1 with data flash memory, Flash Type 3, and Flash Type 4.

The ROM (code and constants) and RAM (global data) sizes are determined by the build-time configuration options set in the module configuration header file.

The values in the table below are confirmed under the following conditions.

Module Revision: r_flash_rx Rev.4.80

Compiler Version: Renesas Electronics C/C++ Compiler Package for RX Family V3.03.00

(The option of "-lang = c99" is added to the default settings of the integrated

development environment.)

GCC for Renesas RX 8.03.00.202102

(The option of "-std = gnu99" is added to the default settings of the integrated

development environment.)

IAR C/C++ Compiler for Renesas RX version 4.20.3

(The default settings of the integrated development environment.)

Configuration Options: The setting of configuration options that are different is described in each table.

Other configuration options are default settings.



Flash Type 1: ROM, RAM and Stack Code Sizes (Maximum Size)										
Memory Used										
		Renesas Compiler		Renesas Compiler GCC IAR Compiler						
	With Without With Without With			With	Without					
		Parameter		Parameter	Parameter	Parameter	Parameter			
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking			
RX130	ROM	3527 bytes	3160 bytes	7276 bytes	6596 bytes	5440 bytes	4936 bytes			
	RAM	3043 bytes		6340 bytes		4807 bytes				
	STACK	112 bytes		-		100 bytes				

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 1

FLASH_CFG_DATA_FLASH_BGO 1

FLASH_CFG_CODE_FLASH_BGO 1

Flash Type 1: ROM, RAM and Stack Code Sizes (Minimum Size)									
		Memory Used							
	Renesas Compiler GCC IAR Compile								
		With	Without	With	Without	With	Without		
		Parameter	Parameter		Parameter	Parameter	Parameter		
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking		
RX130	ROM	1855 bytes	1693 bytes	3872 bytes	3616 bytes	2599 bytes	2392 bytes		
	RAM	61 bytes		64 bytes		43 bytes			
	STACK	52 bytes		-		44 bytes			

Configuration options:

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 0

FLASH CFG DATA FLASH BGO 0

Flash Type 1: ROM, RAM and Stack Code Sizes (Maximum Size)										
Memory Used										
		Renesas Compiler		Renesas Compiler GCC IAR Compiler						
		With Without With Without With			Without					
		Parameter		Parameter	Parameter	Parameter	Parameter			
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking			
RX140	ROM	3468 bytes	3089 bytes	7248 bytes	6536 bytes	5432 bytes	4912 bytes			
	RAM	2965 bytes		6288 bytes		4768 bytes				
	STACK	108 bytes		-		100 bytes				

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 1

FLASH_CFG_DATA_FLASH_BGO 1

FLASH_CFG_CODE_FLASH_BGO 1

Flash Type 1: ROM, RAM and Stack Code Sizes (Minimum Size)								
		Renesas Compiler GCC IAR Compiler						
	With Without With Wi		Without	With	Without			
		Parameter	Parameter		Parameter	Parameter	Parameter	
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking	
RX140	ROM	1872 bytes	1698 bytes	3912 bytes	3616 bytes	2633 bytes	2409 bytes	
	RAM	61 bytes		64 bytes		43 bytes		
	STACK	52 bytes		-		44 bytes		

Configuration options:

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 0

FLASH CFG DATA FLASH BGO 0

Flash Ty	Flash Type 1: ROM, RAM and Stack Code Sizes (Maximum Size)						
		Memory Used	lemory Used				
		Renesas Com	Renesas Compiler GCC IAR Compiler			er	
		With	Without	With	Without	With	Without
		Parameter		Parameter	Parameter	Parameter	Parameter
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking
RX23T*	ROM	3021 bytes	2710 bytes	6056 bytes	5464 bytes	4512 bytes	4088 bytes
	RAM	2767 bytes		5656 bytes		4223 bytes	
	STACK	108 bytes	_	-		100 bytes	

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 1

FLASH_CFG_DATA_FLASH_BGO 1

FLASH_CFG_CODE_FLASH_BGO 1

^{*}Device without data flash

Flash Ty	Flash Type 1: ROM, RAM and Stack Code Sizes (Minimum Size)						
		Memory Used	Memory Used				
		Renesas Com	Renesas Compiler GCC IAR Compiler			er	
		With	Without	With	Without	With	Without
		Parameter	Parameter		Parameter	Parameter	Parameter
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking
RX23T*	ROM	2680 bytes	2382 bytes	5408 bytes	4840 bytes	3848 bytes	3432 bytes
	RAM	2431 bytes		5008 bytes		3558 bytes	
	STACK	52 bytes		-		44 bytes	

Configuration options:

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 1

FLASH_CFG_DATA_FLASH_BGO 0

^{*}Device without data flash

Flash Ty	Flash Type 3: ROM, RAM and Stack Code Sizes (Maximum Size)						
		Memory Use	Memory Used				
		Renesas Co	mpiler	GCC		IAR Compiler	
		With	Without	With	Without	With	Without
		Parameter	Parameter	Parameter	Parameter	Parameter	Parameter
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking
RX64M	ROM	3606 bytes	3132 bytes	7512 bytes	6672 bytes	5648 bytes	5036 bytes
	RAM	3160 bytes		6740 bytes		5017 bytes	
	STACK	220 bytes		-		176 bytes	

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 1

FLASH_CFG_DATA_FLASH_BGO 1

FLASH_CFG_CODE_FLASH_BGO 1

Flash Ty	Flash Type 3: ROM, RAM and Stack Code Sizes (Minimum Size)							
		Memory Use	Memory Used					
		Renesas Co	Renesas Compiler GCC IAR (IAR Compile	AR Compiler	
		With	Without	With	Without	With	Without	
		Parameter	Parameter	Parameter	Parameter	Parameter	Parameter	
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking	
RX64M	ROM	2211 bytes	2022 bytes	4640 bytes	4336 bytes	3247 bytes	2994 bytes	
	RAM	65 bytes		68 bytes		48 bytes		
	STACK	76 bytes		-		56 bytes		

Configuration options:

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 0

FLASH_CFG_DATA_FLASH_BGO 0

Flash Ty	Flash Type 4: ROM, RAM and Stack Code Sizes (Maximum Size)						
		Memory Use	Nemory Used				
		Renesas Co	mpiler	GCC		IAR Compiler	
		With	Without	With	Without	With	Without
		Parameter	Parameter	Parameter	Parameter	Parameter	Parameter
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking
RX65N	ROM	3636 bytes	3148 bytes	7448 bytes	6560 bytes	5556 bytes	4924 bytes
	RAM	3284 bytes		6248 bytes		4739 bytes	
	STACK	204 bytes		-		172 bytes	

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 1

FLASH_CFG_DATA_FLASH_BGO 1

FLASH_CFG_CODE_FLASH_BGO 1

Flash Ty	Flash Type 4: ROM, RAM and Stack Code Sizes (Minimum Size)							
		Memory Use	Memory Used					
		Renesas Co	Renesas Compiler GCC			IAR Compiler		
		With	Without	With	Without	With	Without	
		Parameter	Parameter	Parameter	Parameter	Parameter	Parameter	
Device	Category	Checking	Checking	Checking	Checking	Checking	Checking	
RX65N	ROM	2042 bytes	1853 bytes	4216 bytes	3912 bytes	3008 bytes	2763 bytes	
	RAM	61 bytes		64 bytes		47 bytes		
	STACK	72 bytes		-		52 bytes		

Configuration options:

FLASH_CFG_PARAM_CHECKING_ENABLE 0: Without parameter check, 1: With parameter check

FLASH_CFG_CODE_FLASH_ENABLE 0

FLASH_CFG_DATA_FLASH_BGO 0

2.9 Parameters

This section defines the structure and enumeration used for API function arguments. This section provides common module definitions and definitions that vary depending on flash memory functionality and capacity.

2.9.1 Definitions of Common Arguments

flash interrupt event t event;

} flash_int_cb_args_t;

Structures and enumerations commonly used as module arguments are defined in "r flash rx if.h".

// Interrupt-causing event

```
/* R FLASH Control Function command definitions */
typedef enum _flash_cmd
    FLASH_CMD_RESET, // Resets the flash sequencer

FLASH_CMD_STATUS_GET, // Retrieves the status of the FLASH FIT module API
FLASH_CMD_SET_BGO_CALLBACK, // Registers the callback function
     FLASH_CMD_SWAPFLAG_GET, // Retrieves configuration of the current startup region
     FLASH CMD SWAPFLAG TOGGLE, // Swaps the startup region
     FLASH_CMD_SWAPSTATE_GET, // Retrieves setting of the startup region selection bit FLASH_CMD_SWAPSTATE_SET, // Sets the startup region selection bit FLASH_CMD_ACCESSWINDOW_SET, // Sets the access window boundary
     FLASH_CMD_ACCESSWINDOW_GET, // Retrieves the access window boundary
    FLASH_CMD_LOCKBIT_READ, // Retrieves the access window boundary
FLASH_CMD_LOCKBIT_READ, // Retrieves lockbit information for the specified block
FLASH_CMD_LOCKBIT_WRITE, // Sets the lockbit for the specified block
FLASH_CMD_LOCKBIT_ENABLE, // Enables lockbit protection
FLASH_CMD_LOCKBIT_DISABLE, // Disables lockbit protection
FLASH_CMD_CONFIG_CLOCK, // Provides notification of operating frequency to the
flash sequencer
    FLASH_CMD_ROM_CACHE_ENABLE, // Enables ROM cache
FLASH_CMD_ROM_CACHE_DISABLE, // Disables ROM cache
FLASH_CMD_ROM_CACHE_STATUS, // Retrieves ROM cache status (enabled/disabled)
     FLASH_CMD_SET_NON_CACHED_RANGEO, // Sets the range of RANGEO where cache is disabled
     FLASH_CMD_SET_NON_CACHED_RANGE1, // Sets the range of RANGE1 where cache is disabled
     FLASH CMD GET NON CACHED RANGEO, // Retrieves the setting of RANGEO where cache is
disabled
     FLASH CMD GET NON CACHED RANGE1, // Retrieves the setting of RANGE1 where cache is
disabled
    FLASH_CMD_BANK_TOGGLE, // Swaps the startup bank
     FLASH_CMD_BANK_GET, // Retrieves settings of the current bank selection register
     FLASH CMD END ENUM
                                   // This definition is not used
} flash cmd t;
/* Definitions of R FLASH Control and R FLASH BlankCheck function results
typedef enum flash res
     FLASH RES LOCKBIT STATE PROTECTED, // FLASH CMD LOCKBIT READ result - protected
     FLASH RES LOCKBIT STATE NON PROTECTED, // FLASH CMD LOCKBIT READ result - not
protected
     FLASH RES BLANK,
                                                    // R FLASH BlankCheck result - blank
     FLASH RES NOT BLANK
                                                    // R FLASH BlankCheck result - not blank
} flash res t;
/* Definitions used with FLASH CMD BANK GET command in R FLASH Control function */
typedef enum flash bank
                                = 0,
     FLASH BANK1
                                                             // BANKSEL.BANKSWP is 000
     FLASH_BANK1 = 0,

FLASH_BANK0 = 1,
                                                            // BANKSEL.BANKSWP is 111
     FLASH_BANKO_FFE00000 = 0,
                                                            // BANKSEL.BANKSWP is 000
                                                            // BANKSEL.BANKSWP is 000
     FLASH_BANK1_FFF00000 = 0,
     FLASH BANKO FFF00000 = 1,
                                                             // BANKSEL.BANKSWP is 111
                                                            // BANKSEL.BANKSWP is 111
     FLASH BANK1 FFE00000 = 1
} flash bank t;
```

- *1. The actual definition of flash_block_address_t varies depending on the MCU.
- ^{*2} Used when using the FLASH_CMD_LOCKBIT_READ command.
- *3 Used when using the FLASH_CMD_LOCKBIT_WRITE command.

```
/* Definitions used for specifying sizes of caches being disabled */
typedef enum flash no cache size
      FLASH_NON_CACHED_16_BYTES = 0x10,
FLASH_NON_CACHED_32_BYTES = 0x20,
FLASH_NON_CACHED_64_BYTES = 0x40,
                                                                                              // 16 bytes
                                                                                              // 32 bytes
                                                                                               // 64 bytes
      FLASH NON CACHED 128 BYTES = 0x80,
                                                                                              // 128 bytes
      FLASH NON CACHED 256 BYTES = 0 \times 100,
                                                                                             // 256 bytes
                                                                                             // 512 bytes
      FLASH NON CACHED 512 BYTES = 0x200,
                                                                                             // 1 Kbyte
      FLASH_NON_CACHED_1_KBYTE = 0x400,
FLASH_NON_CACHED_2_KBYTES = 0x800,
                                                                                             // 2 Kbytes
// 4 Kbytes
     FLASH_NON_CACHED_2_KBYTES = 0x800,
FLASH_NON_CACHED_4_KBYTES = 0x1000,
FLASH_NON_CACHED_8_KBYTES = 0x2000,
FLASH_NON_CACHED_16_KBYTES = 0x4000,
FLASH_NON_CACHED_32_KBYTES = 0x8000,
FLASH_NON_CACHED_64_KBYTES = 0x10000,
FLASH_NON_CACHED_128_KBYTES = 0x20000,
FLASH_NON_CACHED_256_KBYTES = 0x40000,
FLASH_NON_CACHED_512_KBYTES = 0x80000
                                                                                             // 8 Kbytes
                                                                                             // 16 Kbytes
                                                                                             // 32 Kbytes
                                                                                             // 64 Kbytes
// 128 Kbytes
// 256 Kbytes
      FLASH NON CACHED 512 KBYTES = 0 \times 80000,
                                                                                              // 512 Kbytes
      FLASH_NON_CACHED_1_MBYTE = 0x100000,
FLASH_NON_CACHED_2_MBYTE = 0x200000
                                                                                             // 1 Mbyte
                                                                                             // 2 Mbytes
} flash non cached size t;
```

2.9.2 Definitions of Arguments that Vary Depending on Flash Memory Functionality and Capacity

The actual definitions of some arguments vary depending on flash memory functionality and capacity.

Argument definitions that are applicable to the RX231, RX64M, and RX72M MCUs are presented here as examples.

File name: r_flash_rx\src\targets\rx231\r_flash_rx231.h

```
/* Definitions related to flash memory block counts, block sizes, minimum programming
sizes, block numbers, and addresses */
- omitted -
#define FLASH NUM BLOCKS DF
                                          (8)
#define FLASH DF MIN PGM SIZE
                                          (1)
#define FLASH_CF_MIN_PGM_SIZE
                                          (8)
#define FLASH CF BLOCK SIZE
                                         (2048)
#define FLASH_DF_BLOCK_SIZE
                                        (1024)
#define FLASH_DF_FULL_SIZE (FLASH_NUM_BLOCKS_DF*FLASH_DF_BLOCK_SIZE)
#define FLASH_DF_FULL_PGM_SIZE (FLASH_DF_FULL_SIZE-FLASH_DF_MIN_PGM_SIZE)
#define FLASH_DF_LAST_VALID_ADDR (FLASH_DF_BLOCK_INVALID-1)
#define FLASH DF HIGHEST VALID BLOCK (FLASH DF BLOCK INVALID-FLASH DF BLOCK SIZE)
#define FLASH_NUM_BLOCKS_CF
                                          (MCU ROM SIZE BYTES / FLASH CF BLOCK SIZE)
                                          (FLASH_NUM_BLOCKS_CF*FLASH_CF_BLOCK_SIZE)
#define FLASH CF FULL SIZE
#define FLASH CF LOWEST VALID BLOCK (FLASH CF BLOCK INVALID + 1)
#define FLASH CF LAST VALID ADDR (FLASH CF LOWEST VALID BLOCK)
- omitted -
typedef enum flash block address
    FLASH_CF_BLOCK_END = 0xffffffff, /* Top of the CS */
FLASH_CF_BLOCK_0 = 0xffffff800, /* 2KB: 0xfffff800 - 0xffffffff */
- omitted -
    FLASH CF BLOCK 255 = 0xFFF80000, /* 2KB: 0xFFF80000 - 0xFFF807FF */
    FLASH CF BLOCK INVALID = (FLASH CF BLOCK 255 - 1),
#endif
- omitted -
    FLASH_DF_BLOCK_0 = 0x00100000, /* 1KB: 0x00100000 - 0x001003ff */
- omitted -
    FLASH DF BLOCK 7 = 0 \times 00101000, /* 1KB: 0 \times 001010000 - 0 \times 00101ffff */
    FLASH DF BLOCK INVALID = 0x00102000
                                               /* 1KB: Can't write beyond 0x00101fff */
} flash block address t;
- omitted -
```

File name: r_flash_rx\src\targets\rx64m\r_flash_rx64m.h

```
/* Definitions related to flash memory block counts, block sizes, minimum programming
sizes, block numbers, and addresses */
- omitted -
#if (MCU_CFG_PART_MEMORY_SIZE == 0x15 )
#define FLASH NUM BLOCKS CF (134)
#elif (MCU CFG PART MEMORY SIZE == 0x13 )
#define FLASH_NUM_BLOCKS_CF (102)
#elif (MCU_CFG_PART_MEMORY_SIZE == 0x10 )
#define FLASH NUM BLOCKS CF (86)
#elif (MCU CFG PART MEMORY SIZE == 0xF )
#define FLASH NUM BLOCKS CF (70)
                                 (1024)
#define FLASH NUM BLOCKS DF
#define FLASH_DF_MIN_PGM_SIZE
                                   (4)
#define FLASH_CF_MIN_PGM_SIZE
                                   (256)
#define FLASH_CF_SMALL_BLOCK_SIZE (8192)
#define FLASH_CF_MEDIUM_BLOCK_SIZE (32768)
#define FLASH_DF_BLOCK_SIZE (64)
#define FLASH_DF_HIGHEST_VALID_BLOCK (FLASH_DF_BLOCK_INVALID - FLASH_DF_BLOCK_SIZE)
- omitted -
typedef enum flash block address
   FLASH_CF_BLOCK_END = 0xffffffff, /* End of Code Flash Area */
FLASH_CF_BLOCK_0 = 0xfffffe000, /* 8KB: 0xfffffe000 - 0xffffffff */
- omitted -
   FLASH CF BLOCK 133 = 0xFFC00000, /* 32KB: 0xFFC00000 - 0xFFC07FFF */
   FLASH CF BLOCK INVALID = (FLASH CF BLOCK 133 - 1), // 0x15 parts 4M ROM
#endif
- omitted -
   FLASH DF BLOCK 0 = 0 \times 00100000, /* 64B: 0 \times 00100000 - 0 \times 0010003F */
- omitted -
   flash block address t;
- omitted -
```

File name: r_flash_rx\src\targets\rx72m\r_flash_rx72m.h

```
/* Definitions related to flash memory block counts, block sizes, minimum programming
sizes, block numbers, and addresses */
- omitted -
#if (MCU_CFG_PART_MEMORY_SIZE == 0xD)
    #if FLASH IN DUAL BANK MODE
         #define FLASH NUM BLOCKS CF (30+8) // 1 Mb per bank dual mode
         #define FLASH NUM BLOCKS CF (62+8) // 2 Mb linear mode
     #endif
#elif (MCU CFG PART MEMORY SIZE == 0x17)
    #if FLASH IN DUAL BANK MODE
         #define FLASH NUM BLOCKS CF (62+8) // 2 Mb per bank dual mode
         #define FLASH NUM BLOCKS CF (126+8) // 4 Mb linear mode
     #endif
#endif
#define FLASH NUM BLOCKS DF
                                                   (512)
#define FLASH DF MIN PGM SIZE
                                                   (4)
#define FLASH CF MIN PGM SIZE
                                                   (128)
#define FLASH_CF_SMALL_BLOCK_SIZE (8192)
#define FLASH_CF_MEDIUM_BLOCK_SIZE (32768)
#define FLASH_CF_LO_BANK_SMALL_BLOCK_ADDR (FLASH_CF_BLOCK_77)
#define FLASH_CF_LOWEST_VALID_BLOCK (FLASH_CF_BLOCK_INVALID + 1)
#define FLASH_DF_BLOCK_SIZE (64)
#define FLASH DF BLOCK SIZE
#define FLASH_DF_HIGHEST_VALID_BLOCK
                                                  (FLASH DF BLOCK INVALID - FLASH DF BLOCK SIZE)
- omitted -
```

```
- omitted -
typedef enum _flash_block_address
 #ifndef FLASH IN DUAL BANK MODE
- omitted -
FLASH CF BLOCK INVALID = (FLASH CF BLOCK 69 - 1),
#else
  FLASH CF BLOCK 70 = 0 \times FFDF8000,
                                /* 32KB: 0xFFDF8000 - 0xFFDFFFFF */
- omitted -
   FLASH CF BLOCK 133 = 0xFFC00000, /* 32KB: 0xFFC00000 - 0xFFC07FFF */
   FLASH_CF_BLOCK_INVALID = (FLASH_CF_BLOCK_133 - 1), /* 'N' parts 4 Mb ROM */
\#endif // > 2M
  se /* DUAL MODE */
FLASH_CF_BLOCK_END = 0xFFFFFFFF, /* End of Code Flash Area */
   FLASH CF HI BANK HI ADDR = FLASH CF BLOCK END,
   FLASH CF BLOCK 0 = 0xffffe000, /* 8KB: 0xffffe000 - 0xffffffff */
- omitted -
   FLASH_CF_HI_BANK_LO_ADDR = FLASH_CF_BLOCK_69,
#endif
   FLASH CF LO BANK HI ADDR = 0xFFDFFFFF, /* START OF NEXT BANK */
  FLASH CF BLOCK 70 = 0xffDfE000, /* 8KB: 0xffDfE000 - 0xffDfffff */
- omitted -
  FLASH CF BLOCK 139 = 0xffC00000, /* 32KB: 0xffC00000 - 0xffC07Fff */
   FLASH CF LO BANK LO ADDR = FLASH CF BLOCK 139,
   FLASH_CF_BLOCK_INVALID = (FLASH_CF_BLOCK_139 - 1),
#endif // 32 blocks for 4M only
#endif // DUAL MODE
   FLASH_DF_BLOCK_0 = 0x00100000, /* 64B: 0x00100000 - 0x0010003F */
- omitted -
  } flash block address t;
- omitted -
```

These definitions are used as the arguments of module API functions. Refer to the descriptions and examples of API functions in section 3 for details on actual usage.

2.10 Return Values

This shows the different values API functions can return. This enumeration is described in the API function prototype declarations as well as in "r_flash_rx_if.h".

2.11 Callback Function

This module calls the callback function specified by the user at timings of FRDYI and FIFERR interrupt generations.

The callback function is configured by storing the address of the user's function in the "pcallback" structure member as described in "2.9 Parameters". When the callback function is called, variables storing the constants described in Table 2.3 through Table 2.5 are passed as arguments.

Use a void pointer variable as the argument of the callback function as arguments are passed as void pointers.

Use values inside the callback function by casting them.

Refer to Example 1 in section 3.6 for example implementations of the callback function.

Table 2.3 Flash Type 1 Callback Function Arguments (enum flash_interrupt_event_t)

Constant Definitions	Description
FLASH_INT_EVENT_ERASE_COMPLETE	Called by the FRDYI interrupt processing and
	indicates completion of the erase process.
FLASH_INT_EVENT_WRITE_COMPLETE	Called by the FRDYI interrupt processing and
	indicates completion of the program process.
FLASH_INT_EVENT_BLANK	Called by the FRDYI interrupt processing and
	indicates that the blank check resulted in a blank
	state.
FLASH_INT_EVENT_NOT_BLANK	Called by the FRDYI interrupt processing and
	indicates that the blank check resulted in a non-
	blank state.
FLASH_INT_EVENT_TOGGLE_STARTUPAREA	Called by the FRDYI interrupt processing and
	indicates completion of swapping the startup
	region.
FLASH_INT_EVENT_SET_ACCESSWINDOW	Called by the FRDYI interrupt processing and
	indicates completion of configuring the access
	window.
FLASH_INT_EVENT_ERR_FAILURE	Called by the FRDYI interrupt processing and
	indicates an error occurred during the program or
	erase process.

Table 2.4 Flash Type 3 Callback Function Arguments (enum flash_interrupt_event_t)

Constant Definitions	Description
FLASH_INT_EVENT_ERASE_COMPLETE	Called by the FRDYI interrupt processing and
	indicates completion of the erase process.
FLASH_INT_EVENT_WRITE_COMPLETE	Called by the FRDYI interrupt processing and
	indicates completion of the program process.
FLASH_INT_EVENT_BLANK*1	Called by the FRDYI interrupt processing and
	indicates that the blank check resulted in a blank
	state.
FLASH_INT_EVENT_NOT_BLANK*1	Called by the FRDYI interrupt processing and
	indicates that the blank check resulted in a non-
	blank state.
FLASH_INT_EVENT_LOCKBIT_WRITTEN	Called by the FRDYI interrupt processing and
FLACUL INTERVENT LOCKET PROTECTED	indicates the setting of lockbit.
FLASH_INT_EVENT_LOCKBIT_PROTECTED	Called by the FRDYI interrupt processing and
FLACIL INT. EVENT LOCKET NON PROTECTED	indicates that lockbit protection is enabled.
FLASH_INT_EVENT_LOCKBIT_NON_PROTECTED	Called by the FRDYI interrupt processing and
FLACILINE EVENT EDD DE ACCECC	indicates that lockbit protection is disabled.
FLASH_INT_EVENT_ERR_DF_ACCESS	Called by the FIFERR interrupt processing and indicates an access violation of data flash
	memory.
FLASH INT EVENT ERR CF ACCESS	Called by the FIFERR interrupt processing and
TEASTI_INT_EVENT_ENT_OF_ACCESS	indicates an access violation of code flash
	memory.
FLASH INT EVENT ERR CMD LOCKED	Called by the FIFERR interrupt processing and
	indicates that commands are locked.
FLASH INT EVENT ERR LOCKBIT SET	Called by the FIFERR interrupt processing and
	indicates an error in a region with lockbit
	protection.
FLASH_INT_EVENT_ERR_FAILURE	Called by the FIFERR interrupt processing and
	indicates an error occurred during the program or
	erase process.

^{*1} The blank check process is only performed on data flash memory.

Table 2.5 Flash Type 4 Callback Function Arguments (enum flash_interrupt_event_t)

Constant Definitions	Description
FLASH_INT_EVENT_ERASE_COMPLETE	Called by the FRDYI interrupt processing and
	indicates completion of the erase process.
FLASH_INT_EVENT_WRITE_COMPLETE	Called by the FRDYI interrupt processing and
	indicates completion of the program process.
FLASH_INT_EVENT_BLANK*1	Called by the FRDYI interrupt processing and
	indicates that the blank check resulted in a blank
	state.
FLASH_INT_EVENT_NOT_BLANK*1	Called by the FRDYI interrupt processing and
	indicates that the blank check resulted in a non-
	blank state.
FLASH_INT_EVENT_TOGGLE_STARTUPAREA	Called by the FRDYI interrupt processing and
	indicates completion of swapping the startup
	region.
FLASH_INT_EVENT_SET_ACCESSWINDOW	Called by the FRDYI interrupt processing and
	indicates completion of configuring the access
ELACULINIT EVENT TOOOLE DANK	window.
FLASH_INT_EVENT_TOGGLE_BANK	Called by the FRDYI interrupt processing and
	indicates completion of swapping of the startup bank.
FLASH INT EVENT ERR DF ACCESS	Called by the FIFERR interrupt processing and
FLASH_INT_EVENT_ERK_DF_ACCESS	indicates an access violation of data flash
	memory.
FLASH_INT_EVENT_ERR_CF_ACCESS	Called by the FIFERR interrupt processing and
TEASTI_INT_EVENT_ENT_OF_ACCESS	indicates an access violation of code flash
	memory.
FLASH INT EVENT ERR SECURITY	Called by the FIFERR interrupt processing and
	indicates a reprogramming of a write-protected
	region of an access window.
FLASH INT EVENT ERR CMD LOCKED	Called by the FIFERR interrupt processing and
	indicates that commands are locked.
FLASH_INT_EVENT_ERR_FAILURE	Called by the FIFERR interrupt processing and
	indicates an error occurred during the program or
	erase process.
*1 The blook sheet was easy is only perferenced as date	· ·

^{*1} The blank check process is only performed on data flash memory.

2.12 Adding the FIT Module to Your Project

This module must be added to each project in which it is used. Renesas recommends the method using the Smart Configurator described in (1), (3) or (5) below. However, the Smart Configurator only supports some RX devices. Please use the methods of (2) or (4) for RX devices that are not supported by the Smart Configurator.

- (1) Adding the FIT module to your project using Smart Configurator in e² studio
 By using the Smart Configurator in e² studio, the FIT module is automatically added to your project.
 Refer to "RX Smart Configurator User's Guide: e² studio (R20AN0451)" for details.
- (2) Adding the FIT module to your project using FIT Configurator in e² studio
 By using the FIT Configurator in e² studio, the FIT module can be automatically added to your
 project. Refer to "Adding Firmware Integration Technology Modules to Projects (R01AN1723)" for
 details.
- (3) Adding the FIT module to your project using Smart Configurator in CS+ By using the Smart Configurator Standalone version in CS+, the FIT module is automatically added to your project. Refer to "RX Smart Configurator User's Guide: CS+ (R20AN0470)" for details.
- (4) Adding the FIT module to your project in CS+ In CS+, manually add the FIT module to your project. Refer to "Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826)" for details.
- (5) Adding the FIT module to your project using Smart Configurator in IAREW By using the Smart Configurator Standalone version, the FIT module is automatically added to your project. Refer to "RX Smart Configurator User Guide: IAREW (R20AN0535)" for details.



2.13 Blocking Mode and Non-blocking Mode

API functions in this module operate in blocking and non-blocking modes.

Blocking mode does not return until the API function has finished processing the flash memory.

Non-blocking mode returns without waiting for the API function to finish processing the flash memory.

2.13.1 Using in Blocking Mode

When using this module in blocking mode, set configuration options as shown below. Set FLASH CFG DATA FLASH BGO and FLASH CFG CODE FLASH BGO to the same value.

- FLASH CFG DATA FLASH BGO: 0
- FLASH CFG CODE FLASH BGO: 0

2.13.2 Using in Non-blocking Mode

When using this module in non-blocking mode, set configuration options as shown below. Set FLASH_CFG_DATA_FLASH_BGO and FLASH_CFG_CODE_FLASH_BGO to the same value.

- FLASH_CFG_DATA_FLASH_BGO: 1
- FLASH_CFG_CODE_FLASH_BGO: 1

Users should not access flash memory regions until flash memory process is complete. If accessed, the flash sequencer generates an error preventing processing from completing properly.

Notification of the result of flash memory processing is sent via the callback function. Register the callback function in advance by executing R_FLASH_Open() and specifying the

FLASH_CMD_SET_BGO_CALLBACK command for the argument of R_FLASH_Control(). (Refer to section 3.6 for details.)

Table 2.6 describes the API functions that send notification of processing results via the callback function.

Table 2.6 API Functions that Send Notifications of Processing Results via the Callback Function

API Function	Processing Result Notification via the Callback Function
R_FLASH_Open(), R_FLASH_Close(), R_FLASH_GetVersion()	Does not send notifications
R_FLASH_Erase(), R_FLASH_BLankCheck(), R_FLASH_Write()	Sends notifications
R_FLASH_Control()	Sends notifications for the following commands:
	FLASH_CMD_SWAPFLAG_TOGGLE
	FLASH_CMD_ACCESSWINDOW_SET
	FLASH_CMD_LOCKBIT_READ
	FLASH_CMD_LOCKBIT_WRITE
	FLASH_CMD_BANK_TOGGLE

A FRDYI or FIFERR interrupt occurs when flash memory processing completes. The callback functions registered by each interrupt are called. Events indicating the completion status are passed to the callback function. Refer to section 2.11 for details on callback functions.

2.14 Region Protection via Access Windows and Lockbits

Regions of each MCU flash memory can be protected by using the access window or lockbit to prevent regions of code flash memory from being unintentionally rewritten. API functions in this module support the following features.

2.14.1 Access Window-based Region Protection

Regions can be protected by using access windows in Flash Type 1 and 4 products.

Access window configurations include specification of the start and end addresses of the blocks defining the region to which the access window is applied.

The region defined by the start and end addresses of the blocks configuring the region to which an access window is applied can be reprogrammed. Make sure to note that it is the other regions that will be write-protected.

All regions are reprogrammable at the time of shipment as access windows are not set by default.

Use R FLASH Control() to configure access windows. Refer to section 3.6 for details.

2.14.2 Lockbit-based Region Protection

Regions can be protected by using lockbits in Flash Type 3 products.

Lockbit configurations include the start address of the blocks defining the region to which lockbit is applied, the number of blocks, and specification of whether lockbit protection is enabled or disabled.

The region defined by the number of specified blocks starting from the specified address configuring the region to which lockbit is applied will be write-protected. Make sure to note that other regions will not be write-protected.

All regions are reprogrammable at the time of shipment as lockbit is not configured by default.

Use R FLASH Control() to configure lockbits. Refer to section 3.6 for details.



2.15 Usage Combined with Existing User Projects

Using the BSP startup disable function, this module can be used in combination with existing user projects.

The BSP startup disable function is a function to add and use this module and other peripheral FIT modules to an existing user project without creating a new project.

BSP and this module (if necessary, other peripheral FIT modules) are incorporated into the existing user project. Even though it is necessary to incorporate BSP, since all startup processing performed by the BSP become disabled, this module and other peripheral FIT modules can be used in combination with startup processing of the existing user project.

There are some settings and notes for using the BSP startup disable function. Refer to "RX Family Board Support Package Module Using Firmware Integration Technology (R01AN1685)" for details.



2.16 Reprogramming Flash Memory

Code required to perform flash memory reprogramming is allocated in code flash memory as illustrated in Figure 2.1 (left figure). As illustrated in Figure 2.1 (right figure), running this code in code flash memory enables reprogramming of the target regions in flash memory.

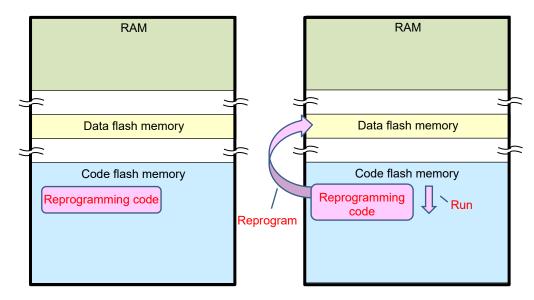


Figure 2.1 Location of Code Required to Perform Flash Memory Reprogramming and Reprogramming Process

Note that, as illustrated in Figure 2.2, the region containing the code required to perform flash memory reprogramming cannot be reprogrammed.

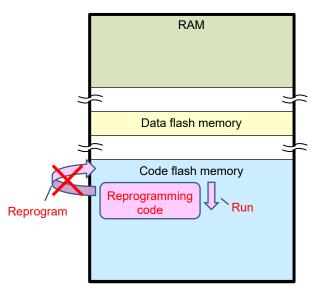


Figure 2.2 Reprogramming of Region Containing Code Required to Perform Flash Memory Reprogramming

2.16.1 through 2.16.3 describe the available methods of reprogramming code flash memory.

2.16.1 Reprogramming Code Flash Memory by Running Code from RAM

As illustrated in Figure 2.3, copying to and then running the code required to reprogram flash memory in RAM enables reprogramming of regions in code flash memory.*1*2

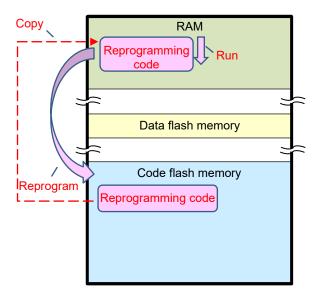


Figure 2.3 Reprogramming Code Flash Memory by Running Code from RAM

Configure the configuration options of this module as follows.

- FLASH_CFG_CODE_FLASH_ENABLE: 1
- FLASH CFG CODE FLASH RUN FROM ROM: 0

This module of Rev. 4.00 or later supports multiple compilers. To use this module, different settings are required for each compiler. For details of the settings appropriate for the compiler to be used, refer to section 5.3.

- The code required to perform flash memory reprogramming is copied to RAM using the R_FLASH_Open() function of this module.

 In addition, it is necessary to reallocate to the RAM such as interrupt vector tables and interrupt handlers for interrupts that may occur when using the API functions of this module. For details, refer to Example 1 in section 3.6.
- ^{*2} Products with multiple regions of code flash memory can reprogram code flash memory without using RAM. Refer to section 2.16.2 for details.

2.16.2 Reprogramming Code Flash Memory by Running Code from Code Flash Memory

Table 2.7 describes the products that support reprogramming of code flash memory by running code from code flash memory. These products support this capability by having multiple regions of code flash memory.

Table 2.7 Products with Multiple Regions of Code Flash Memory

Flash Type	Products with Multiple Regions of Code Flash Memory
3	RX64M*1, RX71M*1
4	RX651*2, RX65N*2, RX66N, RX671, RX72M, RX72N

^{*1} Products with at least 2.5 Mbytes of code flash memory

The capacity of code flash memory regions varies depending on the MCU. As such, the size and boundaries of code flash memory regions are dependent on the MCU. Refer to the hardware section of the applicable user's manual for details.

As illustrated in Figure 2.4, code flash memory can be reprogrammed in products with multiple regions of code flash memory as long as the region is not the region containing the code required to perform flash memory reprogramming.

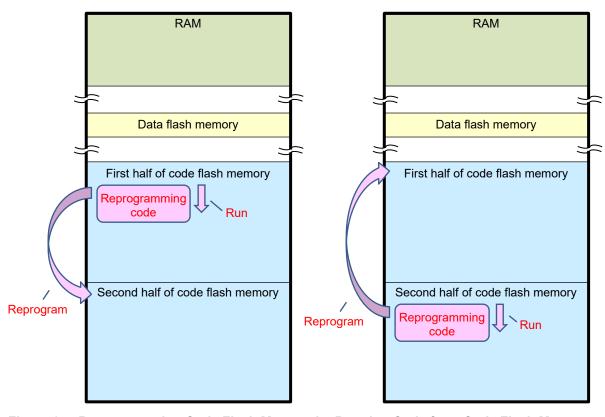


Figure 2.4 Reprogramming Code Flash Memory by Running Code from Code Flash Memory

Configure the configuration options of this module as follows.

- FLASH CFG CODE FLASH ENABLE: 1
- FLASH_CFG_CODE_FLASH_RUN_FROM_ROM: 1

^{*2} Products with at least 1.5 Mbytes of code flash memory

2.16.3 Reprogramming Code Flash Memory by Utilizing the Dual Bank Function

Flash Type 4 products with at least 1.5 Mbytes of code flash memory have the dual bank function.

The dual bank function includes bank mode swapping and bank selection so that programs can be updated while user programs are still running.

Bank mode swapping features a linear mode where the user region in code flash memory is handled as one and a dual mode where it is handled as two bank regions.

Bank selection provides the feature to select the bank region used to start programs when operating in dual mode.

As illustrated in Figure 2.5 (left figure), the bank 0 region containing the code required to perform flash memory reprogramming cannot be reprogrammed, but the bank 1 region can. By swapping banks, the bank 0 region can now be reprogrammed as the bank 1 region now contains the code required to perform flash memory reprogramming as illustrated in Figure 2.5 (right figure).

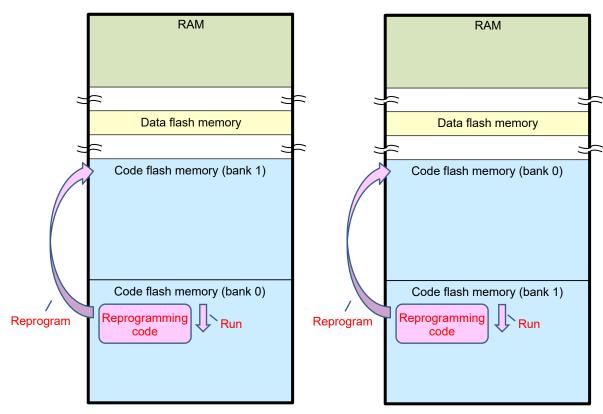


Figure 2.5 Reprogramming Code Flash Memory by Utilizing the Dual Bank Function

To use dual banks, it is necessary to change the constant defined in the configuration file (r_bsp_config.h) of BSP as follows.

BSP_CFG_CODE_FLASH_BANK_MODE: 1 → 0
 The default setting is "1". To operate in dual bank mode, set this constant to "0".

You can change the startup bank in dual mode by specifying the FLASH_CMD_BANK_TOGGLE command as the first argument of the R_FLASH_Control() function. Note that the swap of the startup bank does not take effect until the next MCU reset.

Configure the configuration options of this module as follows.

- FLASH_CFG_CODE_FLASH_ENABLE: 1
- FLASH CFG CODE FLASH RUN FROM ROM: 1

This module of Rev. 4.00 or later supports multiple compilers. To use this module, different settings are required for each compiler. For details of the settings appropriate for the compiler to be used, refer to section 5.3.

3. API Functions

3.1 R_FLASH_Open()

This API function initializes flash modules. Note that this function must be called before any other API function.

Format

```
flash_err_t R_FLASH_Open(void)
```

Parameters

None

Return Values

```
FLASH_SUCCESS /* Successfully initialized. */
FLASH_ERR_BUSY /* A different flash memory process is being executed, try again later. */
FLASH_ERR_ALREADY_OPEN /* Already open. Run R_FLASH_Close(). */
FLASH_ERR_FREQUENCY /* The frequency setting of the Flash clock (FCLK) is invalid. */
FLASH_ERR_HOCO /* The HOCO is not running. */
```

Properties

Prototyped in file "r_flash_rx_if.h".

Description

This API function performs the following processing.

1. Preparing the code required to perform flash memory reprogramming
The code required to perform flash memory reprogramming is allocated depending on the
configuration of configuration options as described in Table 3.1.

Table 3.1 Code Allocations in Relation to Configuration of Configuration Options

Configuration Option	Setting	Code Allocation
FLASH_CFG_CODE_FLASH_ENABLE	0	Code that processes flash memory is
		allocated in code flash memory. However,
		this code does not include code that
		processes code flash memory.
FLASH_CFG_CODE_FLASH_ENABLE	1	Code that processes flash memory is
FLASH_CFG_CODE_FLASH_RUN_FROM_ROM	0	copied into RAM. *1
BSP_CFG_CODE_FLASH_BANK_MODE	0	
FLASH_CFG_CODE_FLASH_ENABLE	1	Code that processes flash memory is
FLASH_CFG_CODE_FLASH_RUN_FROM_ROM	1	allocated in code flash memory.
BSP_CFG_CODE_FLASH_BANK_MODE	0	
FLASH_CFG_CODE_FLASH_ENABLE	1	Code that processes flash memory is
FLASH_CFG_CODE_FLASH_RUN_FROM_ROM	1	allocated in code flash memory.
BSP_CFG_CODE_FLASH_BANK_MODE	1	Code that provides the dual bank function is
		copied into RAM. *1

^{*1} The functionality to reallocate interrupt vector tables or interrupt processing is not included in this API function.

2. Default flash sequencer configuration

For Flash Type 3 and 4 products, the flash sequencer processing clock notification register (FPCKAR) is set with the value of the BSP configuration option (BSP_FCLK_HZ) as the flash sequencer configuration.

The data flash memory access frequency setting register (EEPFCLK) is also configured in the same manner for Flash Type 4 products with at least 1.5 Mbytes of code flash memory.

For the RX64M and RX71M, FCU firmware required to use the flash sequencer is also copied to dedicated RAM (FCURAM).

3. Default interrupt configuration

The interrupts described in section 2.4 are prohibited.

Reentrant

Not allowed



Example

```
flash_err_t err;

/* Initialize the API. */
err = R_FLASH_Open();

/* Check for errors. */
if (FLASH_SUCCESS != err)
{
    . . .
}
```

Special Notes:

None

3.2 R_FLASH_Close()

This API function terminates flash module processing.

Format

```
flash_err_t R_FLASH_Close(void)
```

Parameters

None

Return Values

```
FLASH_SUCCESS /* Successful termination of flash module processing. */
FLASH_ERR_BUSY /* A different flash memory process is being executed,
try again later. */
```

Properties

Prototyped in file "r_flash_rx_if.h".

Description

This API function terminates flash module processing by prohibiting the interrupt described in section 2.4 and setting the module to an uninitialized state.

Reentrant

Not allowed

Example

```
flash_err_t err;

/* Close the driver */
err = R_FLASH_Close();

/* Check for errors. */
if (FLASH_SUCCESS != err)
{
    . . .
}
```

Special Notes:

None

3.3 R_FLASH_Erase()

This API function erases specified blocks in code flash memory or data flash memory.

Format

```
flash_err_t R_FLASH_Erase(
     flash_block_address_t block_start_address,
     uint32_t num_blocks
)
```

Parameters

block start address

Specifies the start address of the blocks to be erased.

"flash_block_address_t" defines the starting block address and block number.

"flash block address t" is defined in "r flash rx\src\targets\<mcu>\r flash <mcu>.h".

num_blocks

Specifies the number of blocks to be erased.

With RX111, RX113, and RX130 products, make sure that regions specified by "block_start_address" and "num_blocks" are not larger than 256 Kbytes.

Return Values

FLASH_SUCCESS	/* Successful completion of erase processing. In non-blocking mode, this indicates that erase processing has started. */
FLASH_ERR_BLOCKS	/* Specified number of blocks is invalid. */
FLASH_ERR_ADDRESS	/* Specified address is invalid. */
FLASH_ERR_BUSY	/* A different flash memory process is being executed, or the module is not initialized. */
FLASH_ERR_FAILURE	/* Erase processing failure. In non-blocking mode, the callback function is not registered. */

Properties

Prototyped in file "r_flash_rx_if.h".

Description

Code flash memory and data flash memory is erased in blocks.

Table 3.2 describes the difference in block sizes by MCU group.

Table 3.2 Block Sizes by MCU Group

MCU Group	Code Flash Memory	Data Flash Memory*3
RX110	1 Kbyte ^{*1}	_*4
RX111	1 Kbyte ^{*1}	1 Kbyte
RX113	1 Kbyte ^{*1}	1 Kbyte
RX130	1 Kbyte ^{*1}	1 Kbyte
RX13T	1 Kbyte ^{*1}	1 Kbyte
RX140	2 Kbytes	256 bytes
RX230, RX231	2 Kbytes ^{*1}	1 Kbyte
RX23E-A	2 Kbytes ^{*1}	1 Kbyte
RX23T	2 Kbytes ^{*1}	*4
RX23W	2 Kbytes*1	1 Kbyte
RX24T	2 Kbytes*1	1 Kbyte
RX24U	2 Kbytes*1	1 Kbyte
RX64M	8 Kbytes, 32 Kbytes*2	64 bytes
RX65N, RX651	8 Kbytes, 32 Kbytes*2	64 bytes*5
RX66N	8 Kbytes, 32 Kbytes*2	64 bytes
RX66T	8 Kbytes, 32 Kbytes*2	64 bytes
RX671	8 Kbytes, 32 Kbytes*2	64 bytes
RX71M	8 Kbytes, 32 Kbytes*2	64 bytes
RX72M	8 Kbytes, 32 Kbytes*2	64 bytes
RX72N	8 Kbytes, 32 Kbytes*2	64 bytes
RX72T	8 Kbytes, 32 Kbytes*2	64 bytes

Defined as FLASH_CF_BLOCK_SIZE in the specific MCU definitions file ("r_flash_rx\src\targets\<mcu>\r_flash_<mcu>\n").

8-Kbytes blocks are defined as FLASH_CF_SMALL_BLOCK_SIZE while 32-Kbytes blocks are defined as FLASH_CF_MEDIUM_BLOCK_SIZE in the specific MCU definitions file ("r flash rx\src\targets\<mcu>\r flash <mcu>\r.").

When this API function is used in non-blocking mode, FRDYI interrupt occurs after blocks for the specified number are erased, and then the callback function is called.

Reentrant

Not allowed



^{*2} Contains both 8-Kb and 32-Kb blocks.

^{*3} Defined as FLASH_DF_BLOCK_SIZE in the specific MCU definitions file ("r_flash_rx\src\targets\<mcu>\r_flash_<mcu>\n").

^{*4} Does not contain any data flash memory.

^{*5} Products with no more than 1 Mbyte of code flash memory do not have data flash memory.

Example

The first argument specifies the starting block address for the erase process.

The second argument specifies the number of blocks to be erased starting from the starting block address for the erase process.

The following code examples shows erase processing for flash memory with multiple blocks specified.

Note that the direction in which blocks are erased varies depending on whether erasing data flash memory or code flash memory and on differences in flash types.

```
flash err t err;
/* Common for Flash Type 1, 3, and 4 products. */
/* Erases data flash memory blocks in order from smaller to larger block numbers starting
from block 5. */
^{\prime\star} The following code causes blocks 5 and 6 in data flash memory to be erased. ^{\star\prime}
err = R FLASH Erase (FLASH DF BLOCK 5, 2);
/* Check for errors. */
if (FLASH SUCCESS != err)
/* For Flash Type 1 products */
/* Erases code flash memory blocks in order from larger to smaller block numbers starting
from block 5. */
^{\prime\star} The following code causes blocks 4 and 5 in code flash memory to be erased. ^{\star\prime}
err = R FLASH Erase (FLASH CF BLOCK 5, 2);
/* Check for errors. */
if (FLASH SUCCESS != err)
{
}
/* For Flash Type 3 and 4 products */
/* Erases code flash memory blocks in order from smaller to larger block numbers starting
from block 5. */
/* The following code causes blocks 5 and 6 in code flash memory to be erased. */
err = R FLASH Erase(FLASH CF BLOCK 5, 2);
/* Check for errors. */
if (FLASH SUCCESS != err)
{
```

Special Notes:

None

3.4 R_FLASH_BlankCheck()

This API function determines if specified code flash memory or data flash memory blocks are blank.

Format

```
flash_err_t R_FLASH_BlankCheck(
    uint32_t address,
    uint32_t num_bytes,
    flash_res_t *blank_check_result
)
```

Parameters

address

Specifies the start address of the region to be processed by the blank check feature.

This parameter must specify a multiple of the minimum programming size of the target flash memory region.

num bytes

Specifies the number of bytes subject to the blank check.

This parameter must specify a multiple of the minimum programming size of the target flash memory region. For RX111, RX113, and RX130 products, make sure that regions specified by "address" and "num_bytes" are not larger than 256 Kbytes.

*blank check result

Specifies the memory address storing the blank check result when using blocking mode. The following are stored as the blank check results.

- FLASH_RES_BLANK: Blank
- FLASH_RES_NOT_BLANK: Not blank

In non-blocking mode, specify any value since this parameter is not used.

Return Values

Return values	
FLASH_SUCCESS	/* Successful completion of blank check processing. In non-blocking mode, this indicates that blank check processing has started. */
FLASH_ERR_FAILURE	/* Blank check processing failure. In non-blocking mode, the callback function is not registered.
FLASH_ERR_BUSY	/* A different flash memory process is being executed, or the module is not initialized. */
FLASH_ERR_BYTES	/* "num_bytes" was either too large, not a multiple of the minimum programming size, or exceeded the maximum range. */
FLASH_ERR_ADDRESS	/* Invalid address was specified. */ /* Address is not a multiple of the minimum programming size or a flash type not supported for blank check was specified. */
FLASH_ERR_NULL_PTR	/* "blank_check_result" for storing blank check results was NULL.*/

Properties

Prototyped in file "r_flash_rx_if.h".

Description

Table 3.3 describes the MCU groups that support blank check.

Table 3.3 MCU Groups Supporting Blank Check

MCU Group	Code Flash Memory	Data Flash Memory
RX110	•	*1
RX111	•	•
RX113	•	•
RX130	•	•
RX13T	•	•
RX140	•	•
RX230, RX231	•	•
RX23E-A	•	•
RX23T	•	*1
RX23W	•	•
RX24T	•	•
RX24U	•	•
RX64M	*2	•
RX65N, RX651	*2	●*3
RX66N	*2	•
RX66T	*2	•
RX671	*2	•
RX71M	_*2	
RX72M	_*2	
RX72N	_*2	
RX72T	_*2	•

^{*1} Does not contain any data flash memory.

The address specified by the first argument and the number of bytes specified by the second argument of this API function must be in multiples of the minimum programming size. The minimum programming size varies depending on the type of both the MCU and flash memory. Refer to Table 3.4 in section 3.5 for details.

If this API function is used in non-blocking mode, the result of the blank check is passed as the argument of the callback function after the blank check is complete.

Reentrant

Not allowed



^{*2} Blank check is not supported.

^{*3} Products with no more than 1 Mbyte of code flash memory do not have data flash memory.

Example

The first argument specifies the start address to be processed by the blank check feature.

The second argument specifies the number of bytes subject to the blank check.

Both of these arguments must be expressed in multiples of the minimum programming size.

```
flash_err_t err;
flash_res_t result;

/* Run the blank check on the first 64 bytes in block 0 of data flash memory. */
err = R FLASH_BlankCheck((uint32_t)FLASH_DF_BLOCK_0, 64, &result);
if (FLASH_SUCCESS != err)
{
    /* Error processing */
}
else
{
    /* Check result */
    if (FLASH_RES_NOT_BLANK == result)
    /* Processing when block is not blank */
        . . .
}
else if (FLASH_RES_BLANK == ret)
{
    /* Processing when block is blank */
        . . .
}
```

Special Notes:

None

RENESAS

3.5 R_FLASH_Write()

This API function reprograms code flash memory or data flash memory.

Format

```
flash_err_t R_FLASH_Write(
          uint32_t src_address,
          uint32_t dest_address,
          uint32_t num_bytes
)
```

Parameters

src_address

Specifies the start address of the buffer storing the data to be written in flash memory.

dest address

Specifies the start address of the region in flash memory to be reprogrammed.

This parameter must specify a multiple of the minimum programming size of the target flash memory region.

num_bytes

Specifies the number of bytes in flash memory to be written.

This parameter must specify a multiple of the minimum programming size of the target flash memory region.

Return Values

Return Values	
FLASH_SUCCESS	/* Successful completion of programming. In non-blocking mode, this indicates that programming has started. */
FLASH_ERR_FAILURE	/* Programming failed due to flash sequencer error. In non-blocking mode, the callback function is not registered. */
FLASH_ERR_BUSY	/* A different flash memory process is being executed, or the module is not initialized. */
FLASH_ERR_BYTES	/* Number of bytes provided was not a multiple of the minimum programming size or exceeds the maximum range. */
FLASH ERR ADDRESS	/* Specified address is invalid. */

Properties

Prototyped in file "r_flash_rx_if.h".

Description

Flash memory regions must be erased before being reprogrammed.

The address specified by the second argument and the number of bytes specified by the third argument of this API function must be in multiples of the minimum programming size. The minimum programming size varies depending on the MCU and flash memory as described in Table 3.4.

Table 3.4 Minimum Programming Sizes by MCU Group

MCU Group	Code Flash Memory*1	Data Flash Memory*2
RX110	4 bytes	_*3
RX111	4 bytes	1 byte
RX113	4 bytes	1 byte
RX130	4 bytes	1 byte
RX13T	4 bytes	1 byte
RX140	8 bytes	1 byte
RX230, RX231	8 bytes	1 byte
RX23E-A	8 bytes	1 byte
RX23T	8 bytes	_*3
RX23W	8 bytes	1 byte
RX24T	8 bytes	1 byte
RX24U	8 bytes	1 byte
RX64M	256 bytes	4 bytes
RX65N, RX651	128 bytes	4 bytes ^{*4}
RX66N	128 bytes	4 bytes
RX66T	256 bytes	4 bytes
RX671	128 bytes	4 bytes
RX71M	256 bytes	4 bytes
RX72M	128 bytes	4 bytes
RX72N	128 bytes	4 bytes
RX72T	256 bytes	4 bytes

Defined as FLASH_CF_MIN_PGM_SIZE in the specific MCU definitions file ("r_flash_rx\src\targets\<mcu>\r_flash_<mcu>.h").

When this API function is used in non-blocking mode, the callback function is called when all write operations are complete.

Reentrant

Not allowed



^{*2} Defined as FLASH_DF_MIN_PGM_SIZE in the specific MCU definitions file ("r_flash_rx\src\targets\<mcu>\r_flash_<mcu>\r_flash_<").

^{*3} Does not contain any data flash memory.

^{*4} Products with no more than 1 Mbyte of code flash memory do not have data flash memory.

Example

The second argument specifies the addresses in flash memory to be reprogrammed.

The third argument specifies the number of bytes to be written in flash memory.

Both of these arguments must be expressed in multiples of the minimum programming size.

```
flash_err_t err;
uint8_t write_buffer[16] = "Hello World...";

/* Write data to internal memory.*/
err = R_FLASH_Write((uint32_t)write_buffer, dst_addr, sizeof(write_buffer));

if (FLASH_SUCCESS != err)
{
    . . .
}
```

Special Notes:

None

3.6 R_FLASH_Control()

This API function perform processing other than programming, erasing, and blank check.

Format

```
flash_err_t R_FLASH_Control(
       flash_cmd_t cmd,
       void
                      *pcfg
```

Parameters

cmd

Specifies the command to execute.

*pcfg

Specifies the required arguments depending on the command specified by argument 1. Set this to NULL if no arguments are required for the particular command.

R

Return Values	
FLASH_SUCCESS	/* Successful completion. In non-blocking mode, this indicates that processing has started successfully. */
FLASH_ERR_ADDRESS	/* Specified address is invalid. */
FLASH_ERR_NULL_PTR	/* NULL was specified even though the second argument was required. */
FLASH_ERR_BUSY	/* A different flash module process is being executed, or the module is not initialized. */
FLASH_ERR_CMD_LOCKED	/* Flash sequencer is in command lock state. */ /* The forced stop command was issued, and the return processing was performed. */
FLASH_ERR_ACCESSW FLASH_ERR_PARAM	/* An access window error occurred. Incorrect region specified. */ /* Invalid parameter was passed. */

Properties

Prototyped in file "r_flash_rx_if.h".

Description

This API function performs processing according to the command specified as an argument. Table 3.5 describes the supported commands by flash type.

Table 3.5 Supported Commands by Flash Type

Type of Command	Command		h Type)
		1	3	4
Common among all flash types				
Retrieve flash module API function running status	FLASH_CMD_STATUS_GET	~	~	~
Register callback function	FLASH_CMD_SET_BGO_CALLBACK	~	~	-
Flash sequencer reset	FLASH_CMD_RESET	~	~	-
Flash sequencer usage frequency notification				
Notify flash sequencer usage frequency	FLASH_CMD_CONFIG_CLOCK	_	~	~
Access window				
Retrieve access window configuration	FLASH_CMD_ACCESSWINDOW_GET			\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Configure access window	FLASH_CMD_ACCESSWINDOW_SET	7		"
Startup program protection				
Retrieve startup region setting	FLASH_CMD_SWAPFLAG_GET			
Swap startup region	FLASH_CMD_SWAPFLAG_TOGGLE	7		\ \ \
Retrieve startup region selection bit setting	FLASH_CMD_SWAPSTATE_GET			
Set startup region selection bit	FLASH_CMD_SWAPSTATE_SET			
Lockbit				
Retrieve lockbit configuration	FLASH_CMD_LOCKBIT_READ			
Set lockbit	FLASH_CMD_LOCKBIT_WRITE		•	
Enable lockbit configuration	FLASH_CMD_LOCKBIT_ENABLE			
Disable lockbit configuration	FLASH_CMD_LOCKBIT_DISABLE			
ROM cache				
Enable ROM cache configuration	FLASH CMD ROM CACHE ENABLE			
Disable ROM cache configuration	FLASH_CMD_ROM_CACHE_DISABLE	'	•	
Retrieve ROM cache configuration	FLASH_CMD_ROM_CACHE_STATUS	*1	*2	
Disable cache				
Set non-cached RANGE0	FLASH_CMD_SET_NON_CACHED_RANGE0		.,	
Set non-cached RANGE1	FLASH_CMD_SET_NON_CACHED_RANGE1	- •		"
Retrieve configuration of non-cached RANGE0	FLASH_CMD_GET_NON_CACHED_RANGE0		*2	*
Retrieve configuration of non-cached RANGE1	FLASH_CMD_GET_NON_CACHED_RANGE1	1		
Dual bank				
Swap banks	FLASH_CMD_BANK_TOGGLE		_	·
Retrieve bank configuration	FLASH_CMD_BANK_GET			*

^{*1} Supported by RX24T and RX24U only.

^{*3} Supported by RX66N, RX671, RX72M, and RX72N only.



^{*2} Supported by RX66T and RX72T only.

Table 3.6 through Table 3.8 describe details of supported commands organized by flash type.

Table 3.6 Details of Commands Supported by Flash Type 1

Command	Contents
FLASH_CMD_STATUS_GET	Retrieves the running state of the flash sequencer for
(Set the argument value to NULL.)	flash memory.
*Refer to Example 3 for usage examples.	This command can be used even while flash memory
	processing is running.
	FLASH_SUCCESS:
	Flash sequencer is not running.
	FLASH_ERR_BUSY:
	Flash sequencer is running.
FLASH_CMD_SET_BGO_CALLBACK	Registers the callback function. This command requires
(Argument: flash_interrupt_config_t *)	operation in non-blocking mode.
*Refer to Example 1 and Example 2 for	
usage examples.	
FLASH_CMD_RESET	Resets the flash sequencer.
(Set the argument value to NULL.)	This command can be used even while flash memory
	processing is running.
FLASH_CMD_ACCESSWINDOW_GET	Retrieves the start and end addresses of the blocks
(Argument: flash_access_window_config_t *)	defining the region to which the access window is applied
*Refer to Example 4 for usage examples.	in code flash memory.
FLASH_CMD_ACCESSWINDOW_SET	Specifies the start and end addresses of the blocks
(Argument: flash_access_window_config_t *)	defining the region to which the access window is applied
*Refer to Example 5 for usage examples.	in code flash memory.
	The start address must be a smaller number than the end address in access window configurations.
	Programming and erase processes cannot be performed on blocks outside the range specified with the start and end addresses.
	Multiple ranges defined by start and end addresses cannot be specified.
	Specify the same start and end addresses to delete an access window configuration.
	When using in non-blocking mode, FRDYI interrupt
	occurs after setting the access window, and then callback
	function is called.
FLASH_CMD_SWAPFLAG_GET	Retrieves the startup region setting.
(Argument: uint32_t *)	0: Startup from the alternate region
*Refer to Example 6 for usage examples.	1: Startup from the default region
FLASH_CMD_SWAPFLAG_TOGGLE	Swaps the startup region.
(Set the argument value to NULL.)	The swapped startup region takes effect after the next
*Refer to Example 7 for usage examples.	reset. When using in non-blocking mode, FRDYI interrupt
	occurs after the startup region is swapped, and then the
	callback function is called.
	Make sure that the
	FLASH_CFG_CODE_FLASH_ENABLE configuration option is set to "1" when using this command.

Command	Contents
FLASH_CMD_SWAPSTATE_GET	Retrieves the value of the startup region selection bit
(Argument: uint8_t *)	(FISR.SAS).
*Refer to Example 8 for usage examples.	FLASH_SAS_EXTRA:
	The startup region selection bit follows the startup region
	configuration.
	FLASH_SAS_DEFAULT:
	Sets the startup region selection bit to the default region.
	FLASH_SAS_ALTERNATE:
	Sets the startup region selection bit to the alternate
	region.
FLASH_CMD_SWAPSTATE_SET	Sets the value of the startup region selection bit
(Argument: uint8_t *)	(FISR.SAS).
*Refer to Example 9 for usage examples.	The set startup region takes effect immediately.
	The default value after a reset is FLASH_SAS_EXTRA.
	FLASH_SAS_EXTRA:
	Follows the configuration of the startup region in extra
	area.
	FLASH_SAS_DEFAULT:
	Temporarily changes the startup region to the default
	region. FLASH SAS ALTERNATE:
	Temporarily changes the startup region to the alternate
	region.
	FLASH SAS SWITCH AREA:
	Swaps the startup region.
FLASH CMD ROM CACHE ENABLE	Enables the code flash memory cache.
(Set the argument value to NULL.)	, i
*Refer to Example 10 for usage examples.	
FLASH_CMD_ROM_CACHE_DISABLE	Disables the code flash memory cache.
(Set the argument value to NULL.)	Call before reprogramming code flash memory.
*Refer to Example 10 for usage examples.	
FLASH_CMD_ROM_CACHE_STATUS	Retrieves the status of code flash memory cache.
(Argument: uint8_t *)	0: Code flash memory cache is disabled
*Refer to Example 10 for usage examples.	1: Code flash memory cache is enabled

Table 3.7 Details of Commands Supported by Flash Type 3

Command	Contents
FLASH_CMD_STATUS_GET	Retrieves the running state of the flash sequencer for
(Set the argument value to NULL.)	flash memory.
*Refer to Example 3 for usage examples.	This command can be used even while flash memory
	processing is running.
	FLASH_SUCCESS:
	Flash sequencer is not running.
	FLASH_ERR_BUSY:
	Flash sequencer is running.
FLASH_CMD_SET_BGO_CALLBACK	Registers the callback function. This command requires
(Argument: flash_interrupt_config_t *)	operation in non-blocking mode.
*Refer to Example 1 and Example 2 for usage	
examples.	
FLASH_CMD_RESET	Resets the flash sequencer.
(Set the argument value to NULL.)	This command can be used even while flash memory
	processing is running.
FLASH_CMD_LOCKBIT_READ	Retrieves the status of the lockbit configuration for the
(Argument: flash_lockbit_config_t *)	specified block in code flash memory.
*Refer to Example 12 for usage examples.	When using in non-blocking mode, FRDYI interrupt
	occurs after the status of the lockbit configuration is
	retrieved, and then the callback function is called. *1
	FLASH_RES_LOCKBIT_STATE_PROTECTED: Protected
	FLASH_RES_LOCKBIT_STATE_NON_PROTECTED:
FLACIL CMD LOCKDIT WRITE	Not protected
FLASH_CMD_LOCKBIT_WRITE	Sets the starting block address and the number of blocks defining the region to which the lockbit is applied
(Argument: flash_lockbit_config_t *) *Refer to Example 12 for usage examples.	in code flash memory.
Refer to Example 12 for usage examples.	For the lockbit configuration, multiple regions specified
	by the starting block address and the number of blocks
	can be set.
	When using in non-blocking mode, FRDYI interrupt
	occurs after setting the lockbit, and then the callback
	function is called. *1
FLASH_CMD_LOCKBIT_ENABLE	Prohibits the program and erase processes from being
(Set the argument value to NULL.)	performed on the blocks in code flash memory set as
*Refer to Example 12 for usage examples.	the lockbit region.
FLASH_CMD_LOCKBIT_DISABLE	Allows the program and erase processes from being
(Set the argument value to NULL.)	performed on the blocks in code flash memory set as
*Refer to Example 12 for usage examples.	the lockbit region.
	The blocks with lockbit set can be erased after using this
	command.
	Note that erasing the blocks with lockbit set also clears
FLACIL CARD DOM CACHE ENABLE	the lockbit configuration for the erased blocks.
FLASH_CMD_ROM_CACHE_ENABLE	Enables the code flash memory cache.
(Set the argument value to NULL.)	
*Refer to Example 10 for usage examples.	Disables the sade flesh many
FLASH_CMD_ROM_CACHE_DISABLE	Disables the code flash memory cache.
(Set the argument value to NULL.)	Call before reprogramming code flash memory.
*Refer to Example 10 for usage examples.	Detrieves the status of sade firsts warmen as the
FLASH_CMD_ROM_CACHE_STATUS	Retrieves the status of code flash memory cache.
(Argument: uint8_t *)	0: Code flash memory cache is disabled
*Refer to Example 10 for usage examples.	1: Code flash memory cache is enabled

Command	Contents
FLASH_CMD_SET_NON_CACHED_RANGE0 (Argument: flash_non_cached_t *) *Refer to Example 11 for usage examples.	Sets the area specified in code flash memory as non-cacheable RANGE0. Caching will be disabled for the specified area.
	Note that running this command while cache is enabled causes the cache to be temporarily disabled.
FLASH_CMD_SET_NON_CACHED_RANGE1 (Argument: flash_non_cached_t *) *Refer to Example 11 for usage examples.	Sets the area specified in code flash memory as non- cacheable RANGE1. Caching will be disabled for the specified area.
	Note that running this command while cache is enabled causes the cache to be temporarily disabled.
FLASH_CMD_GET_NON_CACHED_RANGE0 (Argument: flash_non_cached_t *) *Refer to Example 11 for usage examples.	Retrieves the configuration of non-cacheable RANGE0.
FLASH_CMD_GET_NON_CACHED_RANGE1 (Argument: flash_non_cached_t *) *Refer to Example 11 for usage examples.	Retrieves the configuration of non-cacheable RANGE1.
FLASH_CMD_CONFIG_CLOCK (Argument: uint32_t *)	Provides notification of the frequency used by the flash sequencer. This command is used to change the flash clock (FLCK) speed from the frequency as set by BSP while a program is running. This command is not needed if not

^{*1} Blocks until completion even when operating in non-blocking mode.

Table 3.8 Details of Commands Supported by Flash Type 4

Command	Contents
FLASH_CMD_STATUS_GET	Retrieves the running state of the flash sequencer for
(Set the argument value to NULL.)	flash memory.
*Refer to Example 3 for usage examples.	This command can be used even while flash memory
There's Example of the deage examples.	processing is running.
	FLASH_SUCCESS:
	Flash sequencer is not running.
	FLASH_ERR_BUSY:
	Flash sequencer is running.
FLASH CMD_SET_BGO_CALLBACK	Registers the callback function. This command requires
(Argument: flash_interrupt_config_t *)	operation in non-blocking mode.
*Refer to Example 1 and Example 2 for usage	
examples.	
FLASH CMD RESET	Resets the flash sequencer.
(Set the argument value to NULL.)	This command can be used even while flash memory
(Oct the argument value to NOLL.)	processing is running.
FLASH CMD ACCESSWINDOW GET	Retrieves the start and end addresses of the blocks
(Argument: flash_access_window_config_t *)	defining the region to which the access window is
	applied in code flash memory.
*Refer to Example 4 for usage examples.	
FLASH_CMD_ACCESSWINDOW_SET	Specifies the start and end addresses of the blocks
(Argument: flash_access_window_config_t *)	defining the region to which the access window is
*Refer to Example 5 for usage examples.	applied in code flash memory.
	The start address must be a smaller number than the
	end address in access window configurations.
	Programming and erase processes cannot be performed
	on blocks outside the range specified with the start and
	end addresses.
	Multiple ranges defined by start and end addresses
	cannot be specified.
	Specify the same start and end addresses to delete an
	access window configuration. When using in non-blocking mode, FRDYI interrupt
	occurs after setting the access window, and then
	callback function is called. *1
FLASH_CMD_SWAPFLAG_GET	Retrieves the startup region setting.
(Argument: uint32_t *)	0: Swaps the configuration of startup regions 0 and 1.
*Refer to Example 6 for usage examples.	
nelei to example o loi usage examples.	1: Keeps the configuration of startup regions 0 and 1 to the defaults.
FLASH CMD SWADELAC TOCCLE	
FLASH_CMD_SWAPFLAG_TOGGLE (Set the argument value to NULL)	Swaps the startup region. The swapped startup region takes effect after the next
(Set the argument value to NULL.)	
*Refer to Example 7 for usage examples.	reset. When using in non-blocking mode, FRDYI
	interrupt occurs after the startup region is swapped, and then the callback function is called. *1
FLASH CMD SWAPSTATE GET	Retrieves the value of the startup region selection bit
(Argument: uint8 t *)	(FSUACR.SAS) when operating in linear mode.
	This command cannot be used in dual mode.
*Refer to Example 8 for usage examples.	FLASH SAS SWAPFLG:
	The startup region selection bit follows the startup region
	configuration.
	FLASH SAS DEFAULT:
	Sets the startup region selection bit to startup region 0.
	FLASH SAS ALTERNATE:
	Sets the startup region selection bit to startup region 1.
	Deta the startup region selection bit to startup region 1.

Command	Contents
FLASH_CMD_SWAPSTATE_SET	Sets the value of the startup region selection bit
(Argument: uint8_t *)	(FSUACR.SAS) when operating in linear mode.
*Refer to Example 9 for usage examples.	The set startup region takes effect immediately.
	The default value after a reset is
	FLASH_SAS_SWAPFLG.
	This command cannot be used in dual mode.
	FLASH_SAS_SWAPFLG:
	Follows the configuration of the startup region in option
	settings memory.
	FLASH_SAS_DEFAULT:
	Temporarily changes the startup region to startup region 0.
	FLASH_SAS_ALTERNATE:
	Temporarily changes the startup region to startup region
	1.
	FLASH_SAS_SWITCH_AREA:
	Swaps the startup region.
FLASH CMD ROM CACHE ENABLE	Enables the code flash memory cache.
(Set the argument value to NULL.)	, and the second
*Refer to Example 10 for usage examples.	
FLASH_CMD_ROM_CACHE_DISABLE	Disables the code flash memory cache.
(Set the argument value to NULL.)	Call before reprogramming code flash memory.
*Refer to Example 10 for usage examples.	
FLASH_CMD_ROM_CACHE_STATUS	Retrieves the status of code flash memory cache.
(Argument: uint8_t *)	0: Code flash memory cache is disabled
*Refer to Example 10 for usage examples.	1: Code flash memory cache is enabled
FLASH_CMD_SET_NON_CACHED_RANGE0	Sets the area specified in code flash memory as non-
(Argument: flash_non_cached_t *)	cacheable RANGE0. Caching will be disabled for the
*Refer to Example 11 for usage examples.	specified area.
	Note that running this command while cache is enabled causes the cache to be temporarily disabled.
FLASH_CMD_SET_NON_CACHED_RANGE1	Sets the area specified in code flash memory as non-
(Argument: flash_non_cached_t *)	cacheable RANGE1. Caching will be disabled for the
*Refer to Example 11 for usage examples.	specified area.
	Note that running this command while cache is enabled
FLACUL OND OFT NON OCCUPE TO SEE	causes the cache to be temporarily disabled.
FLASH_CMD_GET_NON_CACHED_RANGE0	Retrieves the configuration of non-cacheable RANGE0.
(Argument: flash_non_cached_t *)	
*Refer to Example 11 for usage examples.	
FLASH_CMD_GET_NON_CACHED_RANGE1	Retrieves the configuration of non-cacheable RANGE1.
(Argument: flash_non_cached_t *)	
*Refer to Example 11 for usage examples. FLASH_CMD_BANK_TOGGLE*2	This command cannot be used in linear mode.
(Set the argument value to NULL.)	Swaps the startup bank when operating in dual mode.
*Refer to Example 13 for usage examples.	The swap of the startup bank takes effect after the next
Telef to Example 15 for usage examples.	reset.
	When using in non-blocking mode, FRDYI interrupt
	occurs after setting the bank selection register
	(BANKSEL), and then the callback function is called. *1

Command	Contents
FLASH_CMD_BANK_GET*2	This command cannot be used in linear mode.
(Argument: flash_bank_t *)	Retrieves the current startup bank setting from the bank
*Refer to Example 13 for usage examples.	selection register (BANKSEL) when operating in dual mode.
	FLASH_BANK0: 1
	FLASH_BANK1: 0
FLASH_CMD_CONFIG_CLOCK	Provides notification of the frequency used by the flash
(Argument: uint32_t *)	sequencer.
	Also sets the read speed for data flash memory. *2
	This command is used to change the flash clock (FLCK)
	speed from the frequency as set by BSP while a
	program is running. This command is not needed if not
	changing the flash clock (FCLK).

^{*1} Blocks until completion even when operating in non-blocking mode.

^{*2} Only supported on products with at least 1.5 Mbyte of code flash memory.

Example 1: Writing to code flash memory in non-blocking mode

To use flash module API functions in non-blocking mode, set both configuration options FLASH_CFG_DATA_FLASH_BGO and FLASH_CFG_CODE_FLASH_BGO to "1".

To program code flash memory by running code from RAM, set the configuration option FLASH_CFG_CODE_FLASH_ENABLE to "1". Also vector tables of possible interrupts must be relocated to RAM.

The registered callback function can be used by running R_FLASH_Open (), using R_FLASH_Control () to register the callback function, and then running a flash module API function (R_FLASH_Write (), R_FLASH_Erase (), or R_FLASH_BlankCheck ()).

```
/* Region in RAM storing vector tables */
static uint32 t ram vect table[256];
void func (void)
    flash err t err;
    flash_interrupt_config_t cb_func_info;
    uint32 t *pvect table;
    /* Relocate interrupt vector tables in RAM */
    /* Directly set the FRDYI interrupt function address into
ram vect table[23]. */
    /* Please consider the method according to the user's system. */
    pvect table = (uint32 t *) sectop("C$VECT");
    ram vect table[23] = pvect table[23]; /* FRDYI Interrupt function copy */
    set intb((void *)ram_vect_table);
    /* Initialize the API. */
    err = R FLASH Open();
    /* Check for errors. */
    if (FLASH SUCCESS != err)
    {
        /* Handle error */
    /* Set callback function and interrupt priority */
    cb func info.pcallback = u cb function;
    cb_func_info.int_priority = 1;
    err = R FLASH Control(FLASH CMD SET BGO CALLBACK, (void *) &cb func info);
    if (FLASH SUCCESS != err)
        /* Handle error */
    }
    /* Perform operations on code flash memory */
    do rom operations();
    ... (omission)
```

```
#pragma section FRAM
void u_cb_function(void *event) /* Callback function */
{
    flash_int_cb_args_t *ready_event = event;

    /* Perform ISR callback functionality here */
    ... (omission)
}

void do_rom_operations(void)
{
    /* Set code flash memory access window, toggle startup area flag */
    /* Swap boot blocks, erase, blank check, or programming processing here */
    ... (omission)
}
#pragma section
```

Example 2: Writing to data flash memory in non-blocking mode

To use flash module API functions in non-blocking mode, set both configuration options FLASH_CFG_DATA_FLASH_BGO and FLASH_CFG_CODE_FLASH_BGO to "1".

To program data flash memory, the code for reprogramming to flash memory can be ran in code flash memory.

The registered callback function can be used by running R_FLASH_Open (), using R_FLASH_Control () to register the callback function, and then running a flash module API function (R_FLASH_Write (), R_FLASH_Erase (), or R_FLASH_BlankCheck ()).

```
void func (void)
    flash err t err;
    flash_interrupt_config_t cb_func_info;
    /* Initialize the API. */
    err = R FLASH Open();
    /* Check for errors. */
    if (FLASH SUCCESS != err)
        /* Handle error */
    }
    /* Set callback function and interrupt priority */
    cb func info.pcallback = u cb function;
    cb func info.int priority = 1;
    err = R FLASH Control(FLASH CMD SET BGO CALLBACK, (void *) &cb func info);
    if (FLASH SUCCESS != err)
        /* Handle error */
    /\star Set erase, blank check, or programming processing of data flash memory
here */
    ... (omission)
void u cb function(void *event) /* Callback function */
    flash int cb args t *ready event = event;
    /* Perform ISR callback functionality here */
    ... (omission)
```

Example 3: Checking running status of flash module API functions

The following example shows the use of R_FLASH_Erase() in non-blocking mode.

```
flash_err_t err;

/* Erase all of data flash */
err = R_FLASH_Erase(FLASH_DF_BLOCK_0, FLASH_NUM_BLOCKS_DF);
if (FLASH_SUCCESS != err)
{
    /* Handle error */
}

/* Check flash module API function running status */
while (FLASH_ERR_BUSY == R_FLASH_Control(FLASH_CMD_STATUS_GET, NULL))
{
    /* Execute any process */
}
```

Example 4: Retrieving the access window configuration area for code flash memory

Example 5: Configuring the access window area for code flash memory

Access window-based region protection is used to prevent configured areas in the code flash memory from being accidentally programmed or erased.

```
flash err t err;
    flash access window config t access info;
    /* Allow programming and erasing of block 3 in code flash memory. */
   access_info.start_addr = (uint32_t) FLASH_CF_BLOCK_3;
   access info.end addr = (uint32 t) FLASH CF BLOCK 2;
   err = R FLASH Control(FLASH CMD ACCESSWINDOW SET, (void *) &access info);
   if (FLASH SUCCESS != err)
      /* Handle error */
   /* Allow programming and erasing of block 2, block 1, and block 0 in code
flash memory. */
   /* Use FLASH CF BLOCK END to specify end address if block 0 is included in
setting range. */
   access_info.start_addr = (uint32 t) FLASH CF BLOCK 2;
   access_info.end_addr = (uint32_t) FLASH_CF_BLOCK END;
   err = R FLASH Control(FLASH CMD ACCESSWINDOW SET, (void *) &access info);
   if (FLASH SUCCESS != err)
      /* Handle error */
    }
```

Example 6: Retrieving the startup region setting

```
flash_err_t err;
uint32_t swap_flag;
err = R FLASH Control(FLASH CMD SWAPFLAG GET, (void *)&swap flag);
if (FLASH SUCCESS != err)
    /* Handle error */
```

Example 7: Swapping the startup region setting

The following example shows how to toggle the active start-up program area.

```
flash err t err;
/* Swap the active area from Default to Alternate or vice versa. */
err = R FLASH Control(FLASH CMD SWAPFLAG TOGGLE, FIT NO PTR);
if (FLASH SUCCESS != err)
{
    /* Handle error */
```

Example 8: Retrieving the value of the startup region selection bit

```
flash err_t err;
err = R FLASH Control(FLASH CMD SWAPSTATE GET, (void *)&swap area);
if (FLASH SUCCESS != err)
   /* Handle error */
```

Example 9: Setting the value of the startup region selection bit

The following example shows how to set the startup region selection bit. The region specified by the startup region selection bit will be used after a reset.

```
flash err t err;
uint8 t
          swap area;
swap area = FLASH SAS SWITCH AREA;
err = R FLASH Control (FLASH CMD SWAPSTATE SET, (void *) &swap area);
if (FLASH SUCCESS != err)
    /* Handle error */
```

Example 10: Enabling/disabling caching of code flash memory

The following example shows a process of enabling code flash memory caching, then disabling caching to perform erase or programming processes, and then re-enabling caching.

```
flash err t err;
uint8 t status;
/* Enable caching */
err = R FLASH Control (FLASH CMD ROM CACHE ENABLE, NULL);
if (FLASH SUCCESS != err)
    /* Handle error */
}
/* Confirm that caching is enabled */
err = R FLASH Control(FLASH CMD ROM CACHE STATUS, &status);
if ((FLASH SUCCESS != err) || (1 != status))
    /* Handle error */
}
... (omission)
/* Disable caching in preparation for programming */
err = R FLASH Control(FLASH CMD ROM CACHE DISABLE, NULL);
if (FLASH SUCCESS != err)
    /* Handle error */
/* Erase, program, and verify new code here */
/* Re-enable caching */
err = R FLASH Control (FLASH CMD ROM CACHE ENABLE, NULL);
if (FLASH SUCCESS != err)
{
    /* Handle error */
```

Example 11: Disabling caching in a specific area of code flash memory

The following shows how to disable caching of a specific area of code flash memory. Up to two areas of disabled caching can be configured, and these areas can overlap.

```
flash err t err;
flash non cached t range;
/* Do not cache fast-instruction fetching or operand access by the CPU */
/* for the first 1 Kbyte of code flash in FLASH_CF_BLOCK_10. */
range.start addr = (uint32 t)FLASH CF BLOCK 10;
range.size = FLASH NON CACHED 1 KBYTE;
range.type mask = FLASH NON CACHED MASK IF | FLASH NON CACHED MASK OA;
err = R FLASH Control(FLASH CMD SET NON CACHED RANGEO, &range);
if (FLASH SUCCESS != err)
{
    /* Handle error */
}
/* Enable caching */
/* This command is eliminated if caching is already enabled. */
err = R FLASH Control(FLASH CMD ROM CACHE ENABLE, NULL);
if (FLASH SUCCESS != err)
    /* Handle error */
}
/* Retrieve non-cached settings for RANGEO */
err = R FLASH Control(FLASH CMD GET NON CACHED RANGEO, &range);
if (FLASH SUCCESS != err)
    /* Handle error */
```

Example 12: Configuring lockbit-based protection on code flash memory

The following example shows a process of setting lockbit on specific blocks in code flash memory, retrieving lockbit information, disabling lockbit-based protection, and then enabling protection.

```
flash err t err;
flash lockbit config t lockbit info;
/* Set lockbit on block 3 in code flash memory */
lockbit info.block start address = FLASH CF BLOCK 3;
lockbit_info.num_blocks = 1;
err = R FLASH Control(FLASH CMD LOCKBIT WRITE, (void *) &lockbit info);
if (FLASH SUCCESS != err)
    /* Handle error */
}
/* Retrieve lockbit information on block 3 in code flash memory */
err = R FLASH Control(FLASH CMD LOCKBIT READ, (void *) &lockbit info);
if ((FLASH SUCCESS != err) ||
     (lockbit info.result != FLASH RES LOCKBIT STATE PROTECTED))
    /* Handle error */
}
/* Disable lockbit-based protection, */
/* which enables erasing or programming of the block with lockbit set. */
err = R FLASH Control(FLASH CMD LOCKBIT DISABLE, NULL);
if (FLASH SUCCESS != err)
{
    /* Handle error */
/* Erasing or programming of the block with lockbit set is now enabled */
/* Enables lockbit-based protection, */
/* which disables erasing or programming of the block with lockbit set. */
err = R FLASH Control(FLASH CMD LOCKBIT ENABLE, NULL);
if (FLASH SUCCESS != err)
{
    /* Handle error */
/* Erasing or programming of the block with lockbit set is now disabled */
```

Example 13: Swapping startup banks

Performs swapping startup banks. The swap of the startup bank takes effect after the next reset.

The startup bank that will take effect after the next reset can be retrieved by the second argument by specifying the FLASH_CMD_BANK_GET command in the first argument of R_FLASH_Control().

If the value of the second argument is FLASH_BANK0, bank 0 will be the startup bank after the next reset. If the value is FLASH_BANK1, bank 1 will be the startup bank after the next reset.

```
flash_err_t err;
flash_bank_t bank_info;

/* Swap the bank selected as the startup bank */
err = R_FLASH_Control(FLASH_CMD_BANK_TOGGLE, NULL);
if (FLASH_SUCCESS != err)
{
    /* Handle error */
}

/* Retrieve the bank selected as the startup bank */
err = R_FLASH_Control(FLASH_CMD_BANK_GET, (void *)&bank_info);
if (FLASH_SUCCESS != err)
{
    /* Handle error */
}

/* The swap of the startup bank takes effect after the next reset */
```

Special Notes:

None

3.7 R_FLASH_GetVersion()

This API function retrieves the version number of the flash module.

Format

```
uint32 t R FLASH GetVersion(void)
```

Parameters

None

Return Values

Version Number

Properties

Prototyped in file "r_flash_rx_if.h".

Description

This API function returns the version number of the flash module. The version number is encoded where the top 2 bytes are the major version number and the bottom 2 bytes are the minor version number. For example, Version 4.25 would be returned as 0x00040019.

Example

Special Notes:

None .

4. Demo Projects

Note that demo projects do not support a compiler other than Renesas Electronics C/C++ Compiler Package for RX Family.

4.1 flash demo rskrx113

This is a simple demo for the RSKRX113 starter kit. The demo uses blocking mode to execute flash erasing, blank check, and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Output).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX113

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30

4.2 flash demo rskrx231

This is a simple demo for the RSKRX231 starter kit. The demo uses blocking mode to execute flash erasing, blank check, and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Output).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX231

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30



4.3 flash demo rskrx23t

This is a simple demo for the RSKRX23T starter kit. The demo uses blocking mode to execute flash erasing, blank check, and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Output).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX23T

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30

4.4 flash_demo_rskrx130

This is a simple demo for the RSKRX130 starter kit. The demo uses blocking mode to execute flash erasing, blank check, and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Output).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX130

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30

4.5 flash_demo_rskrx24t

This is a simple demo for the RSKRX24Tstarter kit. The demo uses blocking mode to execute flash erasing, blank check, and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Output).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX24T

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30



4.6 flash_demo_rskrx65n

This is a simple demo for the RSKRX65N starter kit. The demo uses blocking mode to execute flash erasing, blank check, and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Output).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX65N-1

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30

4.7 flash demo rskrx24u

This is a simple demo for the RSKRX24U starter kit. The demo uses blocking mode to execute flash erasing and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Output).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX24U

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30

4.8 flash_demo_rskrx65n2mb_bank0_bootapp / _bank1_otherapp

This is a simple demo for the dual bank operation of the RX65N-2MB demo board. The demo uses blocking mode and the banks are swapped according to the BANKSEL register value at next reset. The bank 0 application flashes LED0 when it is running. The bank 1 application flashes LED1 when it is running.

Setup and Execution

- 1. Build flash_demo_rskrx65n2mb_bank0_bootapp, and build flash_demo_rskrx65n2mb_bank1_otherapp.
- Download (HardwareDebug) flash_demo_rskrx65n2mb_bank0_bootapp (its debug configuration also downloads the other app).
- 3. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.
- 4. Notice LED0 is flashing. Press the reset switch on the board. Notice LED1 is flashing (banks have swapped and the other application is now running). Continue this reset process if desired.

Boards Supported

RSKRX65N-2MB

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30



4.9 flash demo rskrx64m

This is a simple demo for the RSKRX64M starter kit. The demo uses blocking mode to execute flash erasing and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Output).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX64M

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30

4.10 flash_demo_rskrx64m_runrom

This is a simple demo for the RSKRX64M starter kit. What sets this apart from other demos is that this makes use of the RX64M feature which allows an application to run from one region of code flash while erasing/writing to another. (Most other MCUs require code that could execute during a code flash erase/write to be located in RAM.) The demo uses blocking mode to execute flash erasing and programming. Each write function is verified with a read-back of data. Notice that the typical Linker set up for supporting code flash erase/write (RAM locating) is not necessary in this demo, and that

FLASH CFG CODE FLASH RUN FROM ROM is set to 1 in "r flash rx config.h".

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX64M

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30

4.11 flash demo rskrx66t

This is a simple demo for the RSKRX66T starter kit. The demo uses blocking mode to execute flash erasing and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Symbol file).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX66T

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30



4.12 flash demo rskrx72t

This is a simple demo for the RSKRX72T starter kit. The demo uses blocking mode to execute flash erasing and programming. Each write function is verified with a read-back of data. Note the "pragma section FRAM" for writing to code flash and the corresponding section definitions in the linker (see project Properties->C/C++ Build ->Settings ->Tool Settings (tab) ->Linker ->Section and ->Symbol file).

Setup and Execution

- 1. Compile and download the sample code.
- 2. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.

Boards Supported

RSKRX72T

Evaluation Environment

Version used: BSP Rev. 5.30, FLASH FIT Rev. 4.30

4.13 flash_demo_rskrx72m_bank0_bootapp / _bank1_otherapp

This is a simple demo for the dual bank operation of the RSKRX72M demo board. The demo uses blocking mode and the banks are swapped according to the BANKSEL register value at next reset. The bank 0 application flashes LED0 when it is running. The bank 1 application flashes LED1 when it is running.

Setup and Execution

- 1. Build flash demo rskrx72m bank0 bootapp, and build flash demo rskrx72m bank1 otherapp.
- 2. Download (HardwareDebug) flash_demo_rskrx72m_bank0_bootapp (its debug configuration also downloads the other app).
- 3. Click 'Reset Go' to start the software. If the program stops at main(), press F8 to resume.
- 4. Notice LED0 is flashing. Press the reset switch on the board. Notice LED1 is flashing (banks have swapped and the other application is now running). Continue this reset process if desired.

Boards Supported

RSKRX72M

Evaluation Environment

Version used: BSP Rev.5.30, FLASH FIT Rev.4.30

4.14 Adding a Demo to a Workspace

Demo projects are found in the FITDemos subdirectory of the distribution file for this application note. To add a demo project to a workspace, select *File* >> *Import* >> *General* >> *Existing Projects into Workspace*, then click "Next". From the Import Projects dialog, choose the "Select archive file" radio button. "Browse" to the FITDemos subdirectory, select the desired demo zip file, then click "Finish".

4.15 Downloading Demo Projects

Demo projects are not included in the RX Driver Package. When using the demo project, the FIT module needs to be downloaded. To download the FIT module, right click on this application note and select "Sample Code (download)" from the context menu in the *Smart Brower >> Application Notes* tab.



5. Appendices

5.1 Confirmed Operation Environment

This section describes confirmed operation environment for this module.

Table 5.1 Confirmed Operation Environment (Rev. 4.00)

Item	Contents			
Integrated development environment	Renesas Electronics e ² studio Version 7.3.0 IAR Embedded Workbench for Renesas RX 4.12.1			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 4.08.04.201902 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.12.1 Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.4.00			
Board used	Renesas Starter Kit for RX113 (product No.: R0K505113xxxxxxx)			
	Renesas Starter Kit for RX130 (product No.: RTK5005130xxxxxxxxx)			
	Renesas Starter Kit for RX231 (product No.: R0K505231xxxxxxx)			
	Renesas Starter Kit for RX23T (product No.: RTK500523Txxxxxxxxx)			
	Renesas Starter Kit for RX24T (product No.: RTK500524Txxxxxxxxx)			
	Renesas Starter Kit for RX24U (product No.: RTK500524Uxxxxxxxx)			
	Renesas Starter Kit+ for RX64M (product No.: R0K50564Mxxxxxx)			
	Renesas Starter Kit for RX66T (product No.: RTK50566Txxxxxxxxx)			
	Renesas Starter Kit for RX72T (product No.: RTK5572Txxxxxxxxxxx)			
	Renesas Starter Kit+ for RX65N (product No.: RTK500565Nxxxxxxxx)			
	Renesas Starter Kit+ for RX65N-2MB (product No.: RTK50565Nxxxxxxxxxx)			

Table 5.2 Confirmed Operation Environment (Rev. 4.10)

Item	Contents		
Integrated development environment	Renesas Electronics e ² studio Version 7.3.0		
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99		
Endian	Big endian/little endian		
Revision of the module	Rev.4.10		
Board used	Renesas Solution Starter Kit for RX23W (product No.: RTK5523Wxxxxxxxxxx)		

Table 5.3 Confirmed Operation Environment (Rev. 4.20)

Item	Contents			
Integrated development	Renesas Electronics e ² studio Version 7.3.0			
environment	IAR Embedded Workbench for Renesas RX 4.12.1			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 4.08.04.201902 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.12.1			
	Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.4.20			
Board used	Renesas Starter Kit+ for RX72M (product No.: RTK5572Mxxxxxxxxxx)			

Table 5.4 Confirmed Operation Environment (Rev. 4.30)

Item	Contents			
Integrated development	Renesas Electronics e ² studio Version 7.4.0			
environment	IAR Embedded Workbench for Renesas RX 4.12.1			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 4.08.04.201902 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.12.1			
	Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.4.30			
Board used	RX13T CPU Card (product No.: RTK0EMXA10xxxxxxxxx)			

Table 5.5 Confirmed Operation Environment (Rev. 4.40)

Item	Contents			
Integrated development	Renesas Electronics e ² studio Version 7.5.0			
environment	IAR Embedded Workbench for Renesas RX 4.12.1			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00			
	Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 4.08.04.201902 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.12.1			
	Compiler option: The default settings of the integrated development			
	environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.4.40			
Board used	Renesas Solution Starter Kit for RX23E-A (product No.: RTK0ESXB10xxxxxxxxx)			

Table 5.6 Confirmed Operation Environment (Rev. 4.50)

Item	Contents			
Integrated development	Renesas Electronics e ² studio Version 7.5.0			
environment	IAR Embedded Workbench for Renesas RX 4.12.1			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 4.08.04.201902 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.12.1			
	Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.4.50			
Board used	Renesas Starter Kit+ for RX72N (product No.: RTK5572Nxxxxxxxxxxx)			

Table 5.7 Confirmed Operation Environment (Rev. 4.70)

Item	Contents			
Integrated development	Renesas Electronics e ² studio 2021-01			
environment	IAR Embedded Workbench for Renesas RX 4.14.1			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.02.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 8.3.0.202002 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.14.1 Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.4.70			
Board used	Renesas Starter Kit+ for RX671 (product No.: RTK55671xxxxxxxxxxx)			

Table 5.8 Confirmed Operation Environment (Rev. 4.80)

Item	Contents			
Integrated development	Renesas Electronics e ² studio 2021-07			
environment	IAR Embedded Workbench for Renesas RX 4.20.3			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.03.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 8.3.0.202102 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.20.3 Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.4.80			
Board used	Target Board for RX140 (product No.: RTK5RX140xxxxxxxxx)			

5.2 Troubleshooting

(1) Q: I have added this module to the project and built it. Then I got the error: Could not open source file "platform.h".

A: The FIT module may not be added to the project properly. Check if the method for adding FIT modules is correct with the following documents:

- Using CS+:
 - Application note "Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826)"
- Using e² studio:
 - Application note "Adding Firmware Integration Technology Modules to Projects (R01AN1723)"

When using this module, the board support package FIT module (BSP module) must also be added to the project. Refer to the application note "Board Support Package Module Using Firmware Integration Technology (R01AN1685)".

(2) Q: I have added this module to the project and built it. Then I got the error:

"No data flash on this MCU. Set FLASH_CFG_CODE_FLASH_ENABLE to 1 in r_flash_rx_config.h."

A: The setting values in the "r_flash_rx_config.h" file could be incorrect. Review the "r_flash_rx_config.h" file and correct any incorrect values. Refer to "2.7 Configuration Overview" for details.

(3) Q: I have added this module to the project, changed the compiler option and built it. Then a ROM access violation is detected.

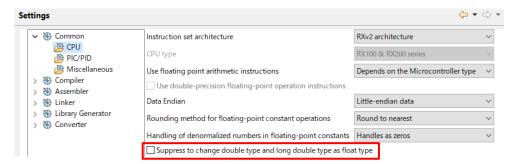
A: To use this module to run codes from RAM to reprogram the code flash memory, all codes used need to be loaded to the RAM.

Depending on the compiler option setting, the loaded destination may be ROM or RAM. If the compiler option needs to be changed, confirm by outputting to a list file the fact that the codes may not be loaded to the ROM as a result of the change of the compiler option.

The following shows an example of a ROM access violation due to a change in the compiler option.

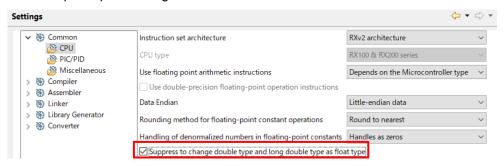


A-1: Default compiler option settings

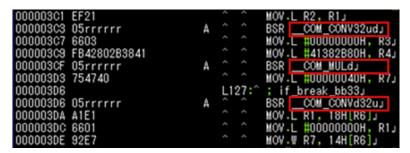


Output result of the list file of the default compiler option settings

A-2: Compiler option change



Output result of the list file after the change in the compiler option



A-1 shows a list file of the default compiler option settings, and A-2 shows a list file after the change in the compiler option.

The difference between the A-1 and A-2 compiler option results in the difference between list file output results.

The red frame parts shown in the list file of A-2 indicate that they have been replaced with runtime library functions.

These runtime library functions are positioned in the "P" section by default and are not loaded to RAM.

For that reason, a ROM access violation will occur during program execution.



5.3 Compiler-Dependent Settings

This module of Rev. 4.00 or later supports multiple compilers. To use this module, different settings are required for each compiler as shown below.

5.3.1 Using Renesas Electronics C/C++ Compiler Package for RX Family

This section describes how to use Renesas Electronics C/C++ Compiler Package for RX Family as the compiler.

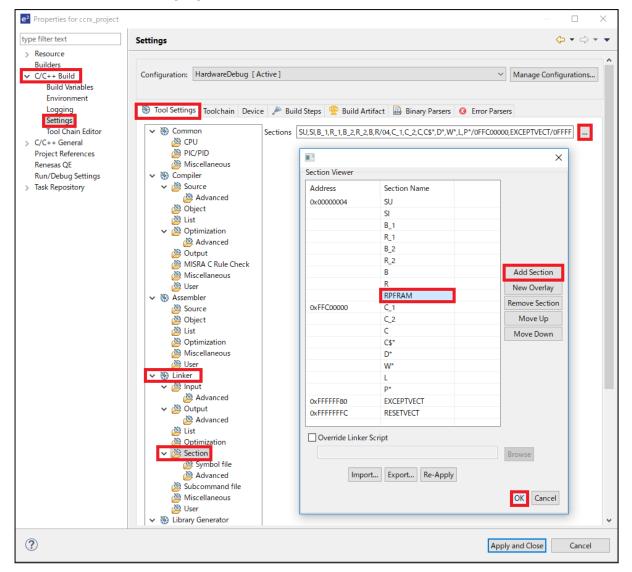
The process of setting up the linker sections and mapping from code flash to RAM need to be done in e^2 studio.



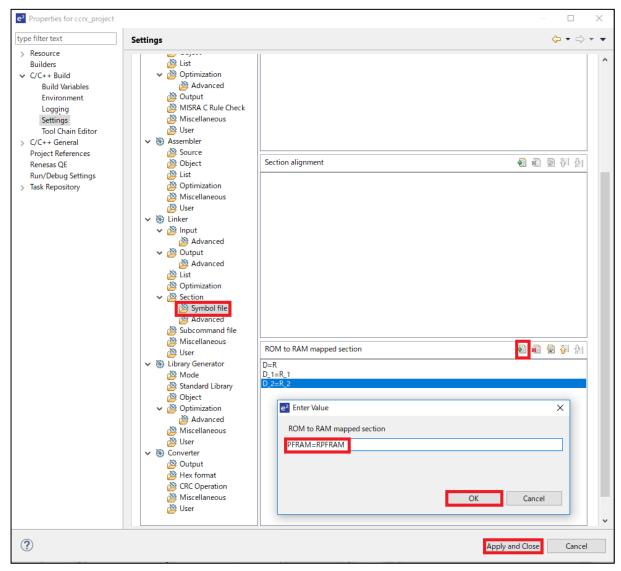
5.3.1.1 Programming Code Flash from RAM

This section describes addition of sections, mapping from code flash to RAM, and placement of programs that operate during code flash re-writing.

- 1. Add a 'RPFRAM' section in a RAM area.
 - (1) In Project Explorer, click the project you want to debug.
 - (2) Click File > Properties to open the Properties window.
 - (3) On the Properties window, click C/C++ Build > Settings.
 - (4) Select the "Tool Settings" tab, click Linker > Section, and click the [...] button to display the Section Viewer window.
 - (5) On the Section Viewer window, click the [Add Section] button to add a 'RPFRAM' section in a RAM area, and then click the [OK] button.



- 2. Map the code flash section (PFRAM) address to the RAM section (RPFRAM) address.
 - (1) After clicking "Symbol file", click the "Add" icon of the section to be mapped from ROM to RAM.
 - (2) On the Enter Value window, enter 'PFRAM=RPFRAM' and then click the [OK] button.
 - (3) Click the [Apply and Close] button.



3. Programs that operate during code flash re-writing such as interrupt callback function, etc. need to be placed in the FRAM section.

```
#pragma section FRAM
/* Function that operates during code flash re-writing */
void func(void){...}

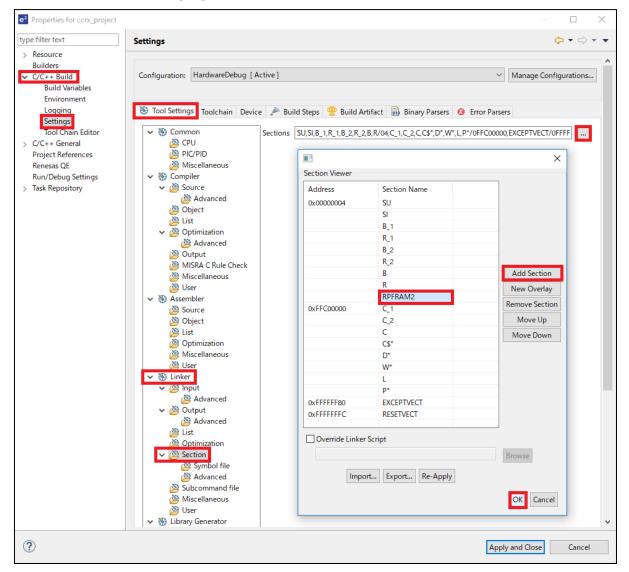
/* Callback function that operates during code flash re-writing */
void cb_func(void){...}

#pragma section
```

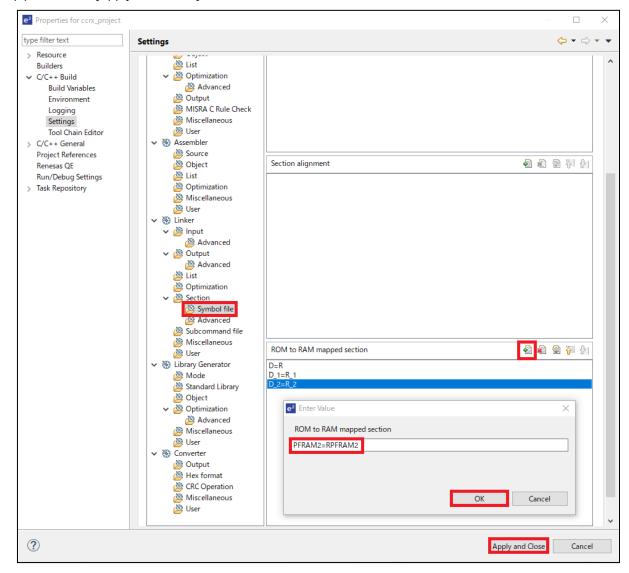
5.3.1.2 Programming Code Flash Using the Dual Bank Function

This section describes addition of sections, mapping from code flash to RAM, and debugging with the dual bank function.

- 1. Add a 'RPFRAM2' section in a RAM area.
 - (1) In Project Explorer, click the project you want to debug.
 - (2) Click File > Properties to open the Properties window.
 - (3) On the Properties window, click C/C++ Build > Settings.
 - (4) Select the "Tool Settings" tab, click Linker > Section, and click the [...] button to display the Section Viewer window.
 - (5) On the Section Viewer window, click the [Add Section] button to add a 'RPFRAM2' section in a RAM area, and then click the [OK] button.



- 2. Map the code flash section (PFRAM2) address to the RAM section (RPFRAM2) address.
 - (1) After clicking "Symbol file", click the "Add" icon of the section to be mapped from ROM to RAM.
 - (2) On the Enter Value window, enter 'PFRAM2=RPFRAM2' and then click the [OK] button.
 - (3) Click the [Apply and Close] button.

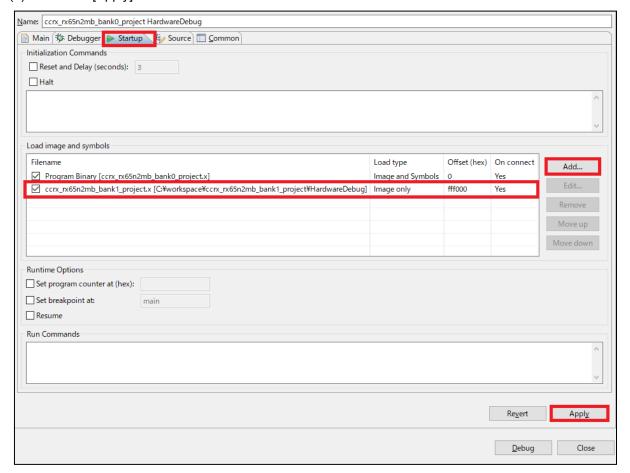


- 3. The following describes how to load objects for two banks when connecting an application related to the dual bank function to a target device and perform debugging. Perform this procedure as required.
 - (1) In Project Explorer, click the project you want to debug.
 - (2) Click Execute > Debug Configuration to open the Debug Configuration window.
 - (3) On the Debug Configuration window, expand the display of the "Renesas GDB Hardware Debugging" debug configuration and click the debug configuration you want to debug.
 - (4) Switch to the "Startup" tab, and click the [Add...] button of "Load image and symbols" on the "Startup" tab.
 - (5) On the Edit Download Module window, specify an object for the other startup bank and then click the [OK] button.
 - (6) Select a "Load type".
 - e²studio can only maintain one debug symbol table at a time. You can set the road type of either of the applications to "Image and Symbols".
 - (7) Specify "Offset".

The "Offset" specification differs depending on the capacity of the code flash memory. For details, refer to the User's Manual for each device used.

The following shows an example when the target device is RX65N and the code flash capacity is 2MB. For "Offset", enter fff00000, for which -1MB is two's complement. By doing so, the application to be assigned to the other startup bank will be loaded into memory 1Mb lower than the values shown in the linker or map file.

(8) Click the [Apply] button.



5.3.2 Using GCC for Renesas RX

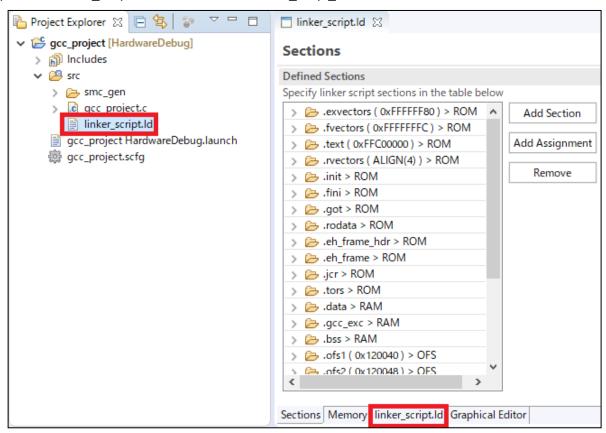
This section describes how to use GCC for Renesas RX as the compiler.

For the linker setting, it is necessary to edit the linker settings file generated by e² studio.

5.3.2.1 Programming Code Flash from RAM

This section describes addition of linker settings and placement of programs that operate during code flash re-writing.

- 1. Add a setting in the linker settings file (linker_script.ld).
 - (1) From Project Explorer, right-click the linker settings file (linker_script.ld), and select "Open".
 - (2) On the linker_script.id window, click the "linker_script_id" tab.



(3) Add the following (a) to (c) in the linker settings file (linker_script.ld).

```
🔲 linker_script.ld 💢
  77
                       .tors :
  78
                       {
  79
                             CTOR_LIST__ = .;
                            . = ALIGN(2);
  80
  81
                               ctors = .;
                            *(.ctors)
  82
  83
                               ctors_end = .;
                              CTOR_END__ = .;
  84
  85
                             DTOR_LIST__ = .;
  86
                              _dtors = .;
                            *(.dtors)
  87
  88
                              _dtors_end = .;
                             _DTOR_END__ = .;
  89
  90
                            . = ALIGN(2);
  91
                            mdata = .;
  92
                          . += _edata -
                                           data;
                         > ROM
  93
  94
                       .pfram ALIGN(4):
  95
                           _PFRAM_start = .;
  96
  97
                            . += _RPFRAM_end - _RPFRAM_start;
  98
                            PFRAM end = .;
  99
                         > ROM
                 0
                       .data : AT(_mdata)
 100
 101
                       {
                            data = .;
 102
                           *(.data)
 103
                            *(.data.*)
 104
                           *(D)
 105
                            *(D_1)
 106
                            *(D_2)
 107
 108
                            edata = .;
 109
                       } > RAM
 110
                       .rpfram ALIGN(4): AT(_PFRAM_start)
 111
 112
                            RPFRAM start = .;
                            *(PFRAM)
 113
 114
                            . = ALIGN(4);
 115
                            RPFRAM end = .;
 116
                         > RAM
 117
                       .gcc_exc :
 118
                            *(.gcc_exc)
 119
 120
                       } > RAM
                                                                    >
Sections | Memory | linker_script.ld | Graphical Editor
```

2. Programs that operate during code flash re-writing such as interrupt callback function, etc. need to be placed in a FRAM section by specifying the FRAM section for each function.

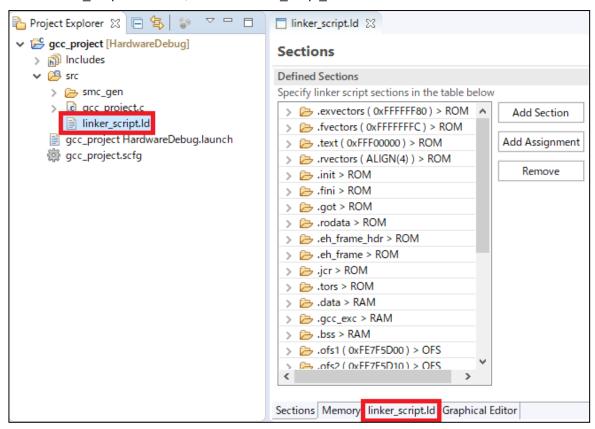
```
__attribute__((section("PFRAM")))
/* Function that operates during code flash re-writing */
void func(void){...}

__attribute__((section("PFRAM")))
/* Callback function that operates during code flash re-writing */
void cb_func(void){...}
```

5.3.2.2 Programming Code Flash Using the Dual Bank Function

This section describes addition of linker settings and debugging with the dual bank function.

- 1. Add a setting in the linker settings file (linker_script.ld).
 - (1) From Project Explorer, right-click the linker settings file (linker_script.ld), and select "Open".
 - (2) On the linker script.id window, click the "linker script id" tab.



(3) Add the following (a) to (c) in the linker settings file (linker_script.ld).

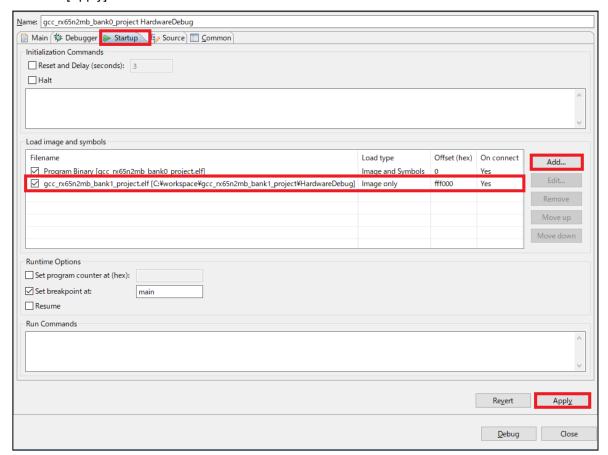
```
🔲 linker_script.ld 💢
                       .tors :
  79
                       {
  80
                             CTOR_LIST_ = .;
  81
                            . = ALIGN(2);
  82
                               _ctors = .;
                            *(.ctors)
  83
                              _ctors_end = .;
  84
                             CTOR_END__ = .;
DTOR_LIST__ = .;
  85
  86
                              dtors = .;
  87
  88
                            *(.dtors)
                            ___dtors_end = .;
  89
                            __DTOR_END__ = .;
  90
  91
                            . = ALIGN(2);
  92
                            _{mdata} = .;
  93
                          . += _edata - _data;
  94
                         > ROM
  95
                 \Theta
                       .pfram2 ALIGN(4):
  96
                           _PFRAM2_start = .;
  98
                            . += _RPFRAM2_end - _RPFRAM2_start;
                            PFRAM2_end = .;
  99
                         > ROM
 100
                       .data : AT(_mdata)
 101
 102
 103
                            data = .;
                           *(.data)
 104
                            *(.data.*)
 105
                            *(D)
 106
 107
                            *(D_1)
 108
                            *(D_2)
 109
                            _{edata} = .;
 110
                       } > RAM
 111
                       .rpfram2 ALIGN(4): AT(_PFRAM2_start)
 112
 113
                            _{RPFRAM2\_start = .;}
                           *(PFRAM2)
 114
 115
                            . = ALIGN(4);
116
                            RPFRAM2_end = .;
117
                         > RAM
118
                        .gcc_exc :
119
120
                            *(.gcc_exc)
121
                       } > RAM
                                                                      >
Sections | Memory | linker_script.ld | Graphical Editor
```

- 2. The following describes how to load objects for two banks when connecting an application related to the dual bank function to a target device and perform debugging. Perform this procedure as required.
 - (1) In Project Explorer, click the project you want to debug.
 - (2) Click Execute > Debug Configuration to open the Debug Configuration window.
 - (3) On the Debug Configuration window, expand the display of the "Renesas GDB Hardware Debugging" debug configuration and click the debug configuration you want to debug.
 - (4) Switch to the "Startup" tab, and click the [Add...] button of "Load image and symbols" on the "Startup" tab.
 - (5) On the Edit Download Module window, specify an object for the other startup bank and then click the [OK] button.
 - (6) Select a "Load type".
 - e²studio can only maintain one debug symbol table at a time. You can set the road type of either of the applications to "Image and Symbols".
 - (7) Specify "Offset".

The "Offset" specification differs depending on the capacity of the code flash memory. For details, refer to the User's Manual for each device used.

The following shows an example when the target device is RX65N and the code flash capacity is 2MB. For "Offset", enter fff00000, for which -1MB is two's complement. By doing so, the application to be assigned to the other startup bank will be loaded into memory 1Mb lower than the values shown in the linker or map file.

(8) Click the [Apply] button.



5.3.3 Using IAR C/C++ Compiler for Renesas RX

This section describes how to use IAR C/C++ Compiler for Renesas RX as the compiler.

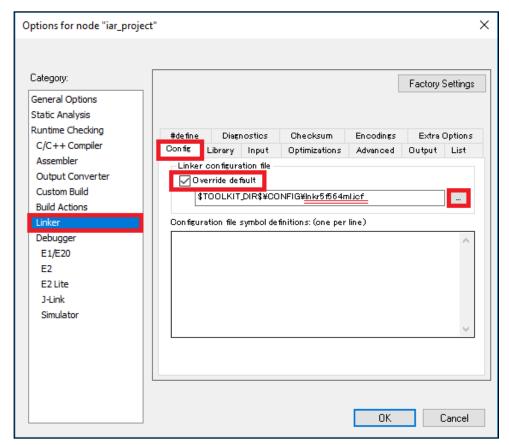
- Using the Smart Configurator Standalone version
 - The Smart Configurator Standalone version is used to generate and use a project for IAR to which this module or BSP is added. Details of Smart Configurator Standalone version are described in the application note "RX Smart Configurator User Guide: IAREW (R20AN0535)".
- Using the FIT Module Importer of IAR Embedded Workbench
 FIT Module Importer of IAR Embedded Workbench is used to generate and use a project for IAR to
 which this module or BSP is added. For details of FIT Module Importer, refer to the latest information
 on the IAR website.

To use this module for a project for IAR, the following settings are required.

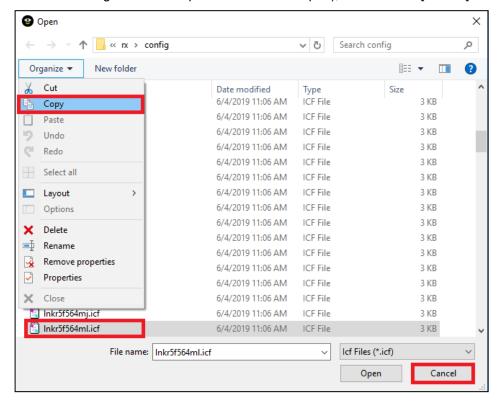
5.3.3.1 Programming Code Flash from RAM

This section describes addition of linker settings and placement of programs that operate during code flash re-writing.

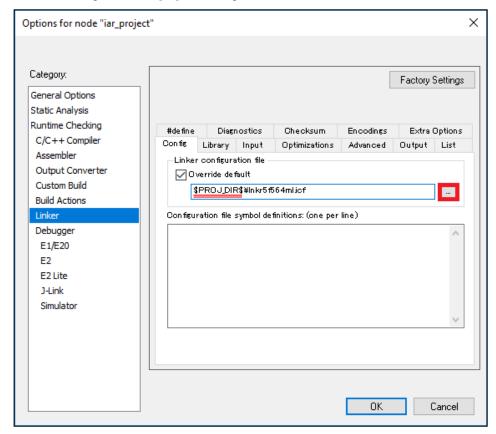
1. Open the Options window of the project for IAR, select "Linker" under "Category:", and select the "Config" tab. Then, after confirming that the "Override default" check box has been selected, click the [...] button.



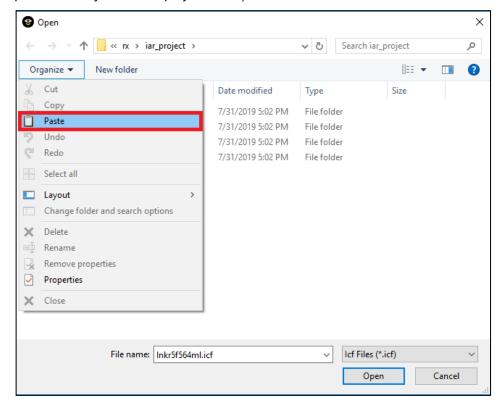
2. On the Open window, copy the .icf file of the target device (the double underlined part of the text box of the linker settings file in the Options window of step 1.), and click the [Cancel] button.



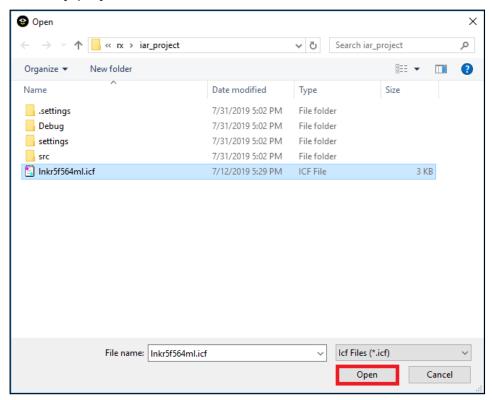
3. Re-write the path to the linker settings file on the Options window to the desired location. (In this example, "\$PROJ_DIR\$" is used as the path variable to place the file directly under the project folder.) After re-writing, click the [...] button again.



4. On the Open window, paste the .icf file of the target device copied in 2 above. (In this example, it is pasted directly under the project folder)



Click the [Open] button.



Now, the default linker settings file was copied and it is ready to edit the copied linker settings file.

5. Copy the following (a) to (d) to add to the replaced linker settings file.

```
    (a) initialize manually { rw section .textrw, section PFRAM };
    (b) define block PFRAM with alignment = 4 { section PFRAM }; define block PFRAM_init with alignment = 4 { section PFRAM_init };
    (c) "ROM32":place in ROM_region32 { ro, block PFRAM_init };
    (d) "RAM32":place in RAM_region32 { rw, ro section D, ro section D_1, ro section D_2, block PFRAM, block HEAP };
```

```
Inkr5f564ml.icf ×
   //-----
    // Linker configuration file template for the Renesas RX microcontroller R5F564MI
    // Compatibility check
    define exported symbol __link_file_version_4 = 1;
    define memory mem with size = 4G;
    define region RAM_region16 = mem:[from 0x00000004 to 0x00007FFF];
    define region RAM_region24 = mem:[from 0x00000004 to 0x0007FFFF];
    define region RAM_region32 = mem:[from 0x00000004 to 0x0007FFFF];
    define region ROM_region16 = mem:[from 0xFFFFF8000 to 0xFFFFFFFF];
    define region ROM_region24 = mem:[from 0xFFC00000 to 0xFFFFFFFF];
    define region ROM_region32 = mem:[from 0xFFC00000 to 0xFFFFFFFF];
    define region DATA FLASH = mem:[from 0x00100000 to 0x0010FFFF];
    initialize manually { rw section .textrw section PFRAM };
    initialize by copy { rw, ro section D, ro section D_1, ro section D_2 };
    initialize by copy with packing = none { section __DLIB_PERTHREAD };
    do not initialize { section .*.noinit };
    define block PFRAM init with alignment = 4
    define block STACKS with fixed order { block USTACK,
                                        block ISTACK };
    place at address mem: 0x00120040
                                      { ro section .option mem }:
    place at address mem:0xFFFFFFFC
                                     { ro section .resetvect };
    place at address mem:0xFFFFFF80
                                      { ro section .exceptvect };
    "ROM16":place in ROM_region16
                                      { ro section .codel6*,
                                        ro section .data16* };
    "RAM16":place in RAM region16
                                      { rw section .datal6*,
                                      rw section __DLIB_PERTHREAD };
{ ro section .code24*,
    "ROM24":place in ROM_region24
                                        ro section .data24* };
    "RAM24":place in RAM region24
                                       { rw section .data24* };
    "ROM32":place in ROM region32
                                        ro,
                                        block PFRAM init
                                        rw,
    "RAM32":place in RAM region32
                                        ro section D,
                                        ro section D_1
                                           section D 2,
                                        block PFRAM,
    "STACKS":place at end of RAM_region32 { block STACKS };
```

6. Programs that operate during code flash re-writing such as interrupt callback function, etc. need to be placed in a FRAM section by specifying the FRAM section for each function.

```
#pragma location="PFRAM"
/* Function that operates during code flash re-writing */
void func(void){...}

#pragma location="PFRAM"
/* Callback function that operates during code flash re-writing
void cb func(void){...}
```

5.3.3.2 Programming Code Flash Using the Dual Bank Function

This section describes addition of linker settings.

After performing items 1. to 4. in section 5.3.3.1, perform the following settings.



```
1. Copy the following (a) to (e) to change and add to the replaced linker settings file.
        Changes to the first address of bank 0 of dual mode.
        define region ROM_region24 = mem:[from 0xFFF00000 to 0xFFFFFFF];
        define region ROM_region32 = mem:[from 0xFFF00000 to 0xFFFFFFFF];
    (b) initialize manually { rw section .textrw, section PFRAM2 };
                                  with alignment = 4 { section PFRAM2 };
    (c) define block PFRAM2
        define block PFRAM2_init with alignment = 4 { section PFRAM2_init };
    (d) "ROM32":place in ROM region32
                                                 { ro,
                                                    block PFRAM2_init };
    (e) "RAM32":place in RAM_region32
                                                 { rw,
                                                    ro section D,
                                                    ro section D 1,
                                                    ro section D 2,
                                                    block PFRAM2,
                                                    block HEAP };
         Inkr5f565ne dual.icf x
            // Linker configuration file template for the Renesas RX microcontroller R5F565NE DUAL
```

```
// Compatibility check
define exported symbol __link_file_version_4 = 1;
define memory mem with size = 4G;
define region RAM_region1 = mem:[from 0x00000004 to 0x0003FFFF];
define region RAM_region2 = mem:[from 0x00800000 to 0x0085FFFF];
define region RAM_region16 = mem:[from 0x00000004 to 0x00007FFF];
define region RAM_region24 = RAM_region1 | RAM_region2;
define region RAM_region32 = RAM_region1 | RAM_region2;
define region STANDBY_RAM = mem:[from 0x000A4000 to 0x000A5FFF];
define region ROM region16 = mem:[from 0xFFFFF8000 to 0xFFFFFFFF];
define region ROM_region24 = mem:[from 0xFFF000000 to 0xFFFFFFFF];
define region ROM_region32 = mem:[from 0xFF7000000 to 0xFFFFFFFFF];
define region DATA FLASH = mem: [from 0x00100000 to 0x00107FFF];
initialize manually { rw section .textrw, section PFRAM2 };
                                                               ro section D_2 };
initialize by copy { rw, ro section D, ro section D
initialize by copy with packing = none { section __DLIB_PERTHREAD };
do not initialize { section .*.noinit };
define block HEAP with alignment = 4, size = _HEAP_SIZE { };
define block USTACK with alignment = 4, size = _USTACK_SIZE { };
define block ISTACK with alignment = 4, size = _ISTACK_SIZE { };
  efine block PFRAM2_init with alignment
define block STACKS with fixed order { block USTACK,
                                            block ISTACK };
{ ro section .codel6*
"ROM16":place in ROM_region16
                                            ro section .data16* };
"RAM16":place in RAM_region16
                                        { rw section .datal6*,
                                          rw section __DLIB_PERTHREAD };
{ ro section .code24*,
"ROM24":place in ROM_region24
                                            ro section .data24* };
"RAM24":place in RAM_region24
                                          { rw section .data24* };
                                          { ro, block PFRAM2 init
"ROM32":place in ROM region32
"RAM32":place in RAM_region32
                                            ro section D,
                                            ro section D 1.
                                             ro section D_2,
"STACKS":place at end of RAM region1 { block STACKS };
```

6. Reference Documents

User's Manual: Hardware

The latest versions can be downloaded from the Renesas Electronics website.

Technical Update/Technical News

The latest information can be downloaded from the Renesas Electronics website.

User's Manual: Development Tools

RX Family C/C++ Compiler CC-RX User's Manual (R20UT3248)

The latest version can be downloaded from the Renesas Electronics website.



Revision History

		Description	n
Rev.	Date	Page	Summary
1.00	July.24.14	_	First edition issued
1.10	Nov.13.14	1, 4	Added RX113 support.
		7	Updated "ROM to RAM" image.
1.11	Dec.11.14	_	Added RX64M to xml support file.
1.20	Dec.22.14	1, 4	Added RX71M support.
1.30	Aug.28.15	All	Updated template. Added RX231 support
		5, 10	Added flash type 3 code flash run-from-rom info.
			Fixed RX64M/71M erase boundary issue.
1.40	Sep.03.15	1, 4	Added RX23T support
			Fixed Big Endian bug in R_DF_Write_Operation() for Flash
			Type 1.
			Fixed FLASH_xF_BLOCK_INVALID values for Flash Type 3.
1.50	Nov.11.15	1, 4	Added RX130 support
1.51	Nov.11.15	_	Repackaged demo with BSP v3.10
1.60	Nov.17.15	1, 5	Added RX24T support
		22, 25	Added ROM cache support
			Fixed incorrect FLASH_CF_BLOCK_INVALID for
			RX210/21A/62N/630/63N/63T in code (Flash Type 2).
1.61	May.20.16	10, 11	Added erase/write/blankcheck BGO support for RX64M/71M
4.00	14 05 40		Fixed lockbit enable/disable commands.
1.62	May.25.16	_	Added lockbit write/read BGO support for RX64M/71M
1.63	Jun.13.16	_	Fixed bug where large flash writes returned success when actually failed (improper timeout handling) on RX64M/71M
1.64	Aug.11.16	_	Fixed RX64M/71M bug where R FLASH Control
1.0	7.43.11.10		(FLASH_CMD_STATUS_GET, NULL) always returned
			BUSY.
			Added #if to exclude ISR code when not in BGO mode.
1.70	Aug.11.16	1, 4-6, 8	Added RX651/RX65N support (Flash Type 4)
		_	Fixed bug in Flash Type 2 that caused erroneous blankcheck
			results.
2.00	Aug.17.16	1, 3, 4, 6-	Added RX230 and RX24T support (Flash Type 1)
		9	Added configuration option for operation without FIT BSP.
			Inserted document sections 2.12.2 thru 2.12.4.
			Modified values for FLASH_CF_LOWEST_VALID_BLOCK
			and
			FLASH_CF_BLOCK_INVALID for Flash TYPE 1.
2.10	Dec.20.16	1, 5-7,	Added RX24U and RX24T-512 support (Flash Type 1)
		11, 13,	Fixed several minor bugs in all flash types and added more
		17, 19,	parameter checking. See History in r_flash_rx_if.h for
		21, 23-26, 31-32	complete list of changes.
		01-02	
3.00	Dec.21.16	8, 9	Merged code common to types 1, 3, and 4 and restructured
		, -	high level code for cleaner operation.
			Modified ROM/RAM size tables.
	<u> </u>	1	1

		Description	n
Rev.	Date	Page	Summary
3.10	Feb.17.17	5-7, 13- 17, 26-28, 35	Added RX65N-2M support. Added sections 2.16 and 2.17.4. Added commands FLASH_CMD_BANK_xxx. Fixed potential "BUSY" return from Flash Type 1 API calls (potential bug with very slow flash). Added clearing of ECC flag during initialization of Flash Type 3.
3.20	Aug.11.17	1, 5, 10-14, 16, 36	Added RX130-512KB support. Added e²studio v6.0.0 differences. Modified driver so mcu_config.h only necessary when not using BSP. Fixed bug in RX65N-2M dual mode operation where sometimes when running in bank 0, performing a bank swap caused application execution to fail.
3.30	Nov.1.17	10, 20 19, 21 32 25	Added FLASH_ERR_ALREADY_OPEN. Added R_FLASH_Close(). Added Flash Type 2 set access window example Added Flash Type 2 blankcheck example.
3.40	Mar.8.18	1, 5, 6 14 14-15 39-40	Added support for RX66T. Added support for new 256K and 384K RX111 and RX24T variants. Updated table numbers in Section 2.14. Added interrupt event enumeration in Section 2.15 Added demos for RDKRX63N, RSKRX66T, and two for RSKRX64M.
3.41	Nov.8.18	6, 31, 36	Added NON_CACHED Control() commands. Added document number of the application note accompanying the sample program of the FIT module to xml file.
3.42	Feb.12.19	38-41	Modified typos in sections 4.1 to 4.12.
3.50	Feb.26.19	1, 5, 6, 31 41	Added support for RX72T. Added demo for RX72T. Fixed write failure bug in RX210 768K and 1M variants.

		Description	n
Rev.	Date	Page	Summary
4.00	Apr.19.19	_	Added support for GCC/IAR compiler.
		1, 6	Deleted the following flash type 2 devices from the target
			device.
			RX210, RX21A, RX220, RX610, RX621, RX62N, RX62T,
			RX62G, RX630, RX631, RX63N, RX63T
		1	Deleted the following documents from Related Documents
			Adding Firmware Integration Technology Modules to e ² studio
			Adding Firmware Integration Technology Modules to CS+ Projects
			Renesas e ² studio Smart Configurator User Guide
		6	Deleted FLASH_CFG_USE_FIT_BSP.
			Deleted FLASH_CFG_FLASH_READY_IPL.
			Deleted FLASH_CFG_IGNORE_LOCK_BITS.
			Added the explanation of FLASH_CFG_DATA_FLASH_BGO.
			Added the explanation of
			FLASH_CFG_CODE_FLASH_BGO.
		7-10	Updated "2.9 Code Size" section.
		11	Deleted the following return values, which are no longer
			necessary, from "2.11 Return Values" section.
			FLASH_ERR_ALIGNED
			FLASH_ERR_BOUNDARY
			FLASH_ERR_OVERFLOW
		12	Updated "2.12 Adding the FIT FLASH Module to Your
			Project" section.
			Added "2.13 Usage Combined with Existing User Projects" section.
		13	Revised and updated as follows the structure of "2.14
			Programming Code Flash from RAM" section.
			"2.14.1 Using Renesas Electronics C/C++ Compiler Package
			for RX Family",
			"2.14.2 Using GCC for Renesas RX",
			"2.14.3 Using IAR C/C++ Compiler for Renesas RX"
		22	Added "2.18.4 Emulator Debug Configuration" section.

		Description		
Rev.	Date	Page	Summary	
Rev. 4.00	Date Apr.19.19	Page Program	Changed as a result of supporting the GCC/IAR compiler. Changed as a result of deletion of FLASH_CFG_USE_FIT_BSP. Changed as a result of deletion of FLASH_CFG_FLASH_READY_IPL. Changed as a result of deletion of FLASH_CFG_IGNORE_LOCK_BITS. Deleted flash type 2 device from target device. Deleted FLASH_ERR_ALIGNED. Deleted FLASH_ERR_BOUNDARY. Deleted FLASH_ERR_OVERFLOW. Added the process to output error when BSP is earlier than	
			Rev.5.00.	
4.10	Jun.07.19	1, 5 7-11 17-18 48 49-50 Program	Added support for RX23W. Updated "2.9 Code Size" section. Updated "2.14.2 Using GCC for Renesas" section. Added "5. Appendices" section. Added "5.1 Confirmed Operation Environment" section. Added "5.2 Troubleshooting" section. Added support for RX23W. Modified FEARL and FSARL register settings. Updated the demo project environment.	
4.20	Jul.19.19	1, 5 47 50 Program	Added support for RX72M. Added "4.13 flash_demo_rskrx72m_bank0_bootapp / _bank1_otherapp" section. Updated "5.1 Confirmed Operation Environment" section. Added support for RX72M. Added the RX72M demo project. Updated the demo project environment.	
			Deleted the warning. Deleted definitions and include, which are no longer used. Granted the volatile declaration to global variables. Modified the section related to dual mode and linear mode. Modified part of Flash Type 4 timeout processing.	

		Description	n
Rev.	Date	Page	Summary
4.30	Sep.09.19	1, 6	Added support for RX13T.
	'	5	Added "2.5 Interrupt Vectors" section.
		7-11	Updated "2.10 Code Size" section.
		14	Modified the following descriptions and moved to "5.3
			Compiler-Dependent Settings".
			"2.14.1 Using Renesas Electronics C/C++ Compiler Package
			for RX Family"
			"2.14.2 Using GCC for Renesas RX"
			"2.14.3 Using IAR C/C++ Compiler for Renesas RX"
		15	Modified "2.18 Dual Bank Operation" section and moved the
			content that depends on the compiler to "5.3 Compiler-
			Dependent Settings".
		42	Updated "5.1 Confirmed Operation Environment" section.
		45-62	Added "5.3 Compiler-Dependent Settings" section.
		Program	Added support for RX13T.
			Modified part of the flash type 1 error processing.
			Modified the copy method of R_FlashCodeCopy() when using
			IAR. Modified the implementation of r_flash_control() to the if_then
			method.
4.40	Sep.27.19	1, 5, 6	Added support for RX23E-A.
4.40	Сор.27.10	23	Added FLASH_ERR_NULL_PTR to Return Values in "3.5
			R_FLASH_BlankCheck()" section.
		42	Updated "5.1 Confirmed Operation Environment" section.
		Program	Added support for RX23E-A.
			Added the NULL check of the 3rd argument of
			r_flash_blankcheck().
4.50	Nov.18.19	1, 5, 6	Added support for RX66N and RX72N.
		5	Added limitations to "2.3 Limitations" section.
		15	Added "2.13 Blocking Mode and Non-blocking Mode" section.
		16 21-37	Deleted "2.17 Operations in BGO Mode" section.
		21-37	Deleted description of Reentrant from "3.2 R_FLASH_Open()", "3.3 R_FLASH_Close()",
			"3.4 R_FLASH_Erase()", "3.5 R_FLASH_BlankCheck()",
			"3.6 R_FLASH_Write()", "3.7 R_FLASH_Control()",
			and "3.8 R FLASH GetVersion()" sections.
		29-32	Modified the content of Description in "3.7
			R_FLASH_Control()" section.
		45	Updated "5.1 Confirmed Operation Environment" section.
		Program	Added support for RX66N and RX72N.
			Supported Doxygen.
			Modified enabling and disabling IEN to use
			R_BSP_InterruptRequestEnable() and
			R_BSP_InterruptRequestDisable().

		Description	n
Rev.	Date	Page	Summary
4.60	Jun.24.20	5-9	Modified the structure and content of "1. Overview" section.
		11	Modified the content of "2.7 Configuration Overview".
		17-23	Modified the structure and content of section "2.9
			Parameters".
		25-27	Added "2.11 Callback Function" section.
		29	Modified the content of "2.13 Blocking Mode and Non-blocking Mode" section.
			Added "2.14 Region Protection via Access Windows and
		30	Lockbits" section.
			Modified the structure and content of "2.16 Reprogramming
		32-36	Flash Memory" section.
		37-68	Modified the structure and content of "3. API Functions"
			section.
		77	Updated "5.2 Troubleshooting" section.
		90	Updated "5.3.3 Using IAR C/C++ Compiler for Renesas RX"
			section.
		Program	Added processing to determine if R_FLASH_Open() has run. Modified the access window processing, including block 0.
			Modified the processing so that the enabling/disabling of IEN
			is performed in the flash module.
			Modified minor content, such as the deletion of unnecessary
			definitions.
4.70	Oct.23.20	1, 5, 6,	Added support for RX671
		34, 42,	
		45, 48, 51	
		76	Updated "5.1 Confirmed Operation Environment" section.
		Program	Added support for RX671
4.80	Apr.23.21	1, 5, 43,	Added support for RX140.
		46, 49	
		12-17	Updated "2.8 Code Size" section.
		25	Added the following return values to "2.10 Return Values"
			section.
			FLASH_ERR_HOCO
		38	Added "Return Values" to "3.1 R_Flash_Open()" section.
		78	Updated "5.1 Confirmed Operation Environment" section.
		Program	Added support for RX140.

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 - A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
- 2. Processing at power-on
 - The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
- 3. Input of signal during power-off state
 - Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
- 4. Handling of unused pins
 - Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
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 - After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
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 - Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
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